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# FAN54300 — USB-Compliant, Dual-Power Input, Single-Cell, Li-Ion Switching Charger with USB-OTG Boost Regulator

#### **Features**

- Fully Integrated, High-Efficiency Charger for Single-Cell Li-lon and Li-Polymer Battery Packs
- Accepts USB or Dedicated Power Input Source
- 5 V, 300 mA Boost Mode for USB OTG from 2.5 to 4.5 V Battery Input
- Charge Voltage Accuracy: ±0.5% at T<sub>A</sub>=25°C ±1% from T<sub>A</sub>=0 to 125°C
- ±5% USB Input Current Regulation Accuracy
- ±5% Charge Current Regulation Accuracy
- 20 V Absolute Maximum Input Voltage
- 9.5 V Maximum Input Operating Voltage on VIN Pin,
   6.5 V Maximum on VBUS Pin
- Up to 1.5 A Maximum Charge Rate
- Programmable Charge and Mode through High-Speed I<sup>2</sup>C Interface (3.4 Mb/s) with Fast Mode Plus Compatibility
  - Input Current
  - Fast-Charge / Termination Current
  - Charger Voltage
  - Safety Timer
  - Termination Enable
- 3 MHz Synchronous Buck PWM Controller with Wide Duty Cycle Range
- Small Footprint, 1 μH, External Inductors
- Safety Timer with Reset Control
- Weak Input Sources Accommodated by Reducing Charging Current to Maintain Minimum V<sub>BUS</sub> Voltage
- Low Reverse Leakage from Battery Drain to VBUS or VIN
- Programmable LED Drive for Charge Indication
- Register and Slave Addresses Compatible with FAN540X and FAN542X Families

## Description

The FAN54300 combines two highly integrated switch-mode chargers and a boost regulator to minimize single-cell Li-lon charging time from a USB and/or auxiliary power source.

Charging parameters and operating modes are programmable through an I<sup>2</sup>C Bus® interface that operates up to 3.4 Mbps. The charger and boost regulator circuits switch at 3 MHz to minimize the size of the external passive components.

The FAN54300 provides battery charging in three phases: conditioning, constant current, and constant voltage.

To ensure USB compliance and minimize charging time, the USB input current is limited to the value set through the  $I^2C$  host. Charge termination is determined by a programmable minimum current level. A safety timer with reset control provides a safety backup for the  $I^2C$  host.

The IC automatically restarts the charge cycle when the battery falls below an internal threshold. If the input source is removed, the IC enters a high-impedance mode, with leakage from the battery to the input prevented. Charge status is reported back to the host through the I<sup>2</sup>C port. Charge current is reduced when the die temperature reaches 120°C.

The FAN54300 can operate as a boost regulator on command from the system. The boost regulator includes a soft-start that limits inrush current from the battery.

The FAN54300 is available in a 30-bump, 0.4 mm pitch, wafer-level, chip-scale package (WLCSP).

## **Applications**

- Cell Phones, Smart Phones, PDAs
- Digital Cameras
- Portable Media Players

## **Ordering Information**

Part Number	Temperature Range	Package	Packing
FAN54300UCX	-40 to 85°C	30-Ball, WLCSP, 5x6 Array, 0.4mm Pitch, 586 µm Package Height	Tape and Reel

**Table 1. Feature Summary** 

Part Number	Automatic Charge	Battery Absent Charge		
FAN54300	Yes	No		

## **Typical Application**

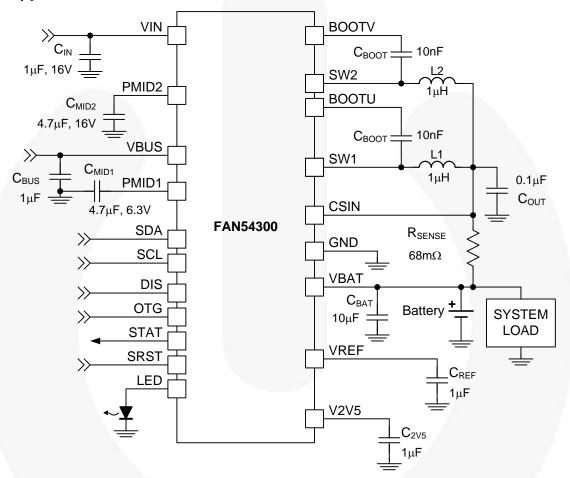


Figure 1. Typical Application

## **Block Diagrams**

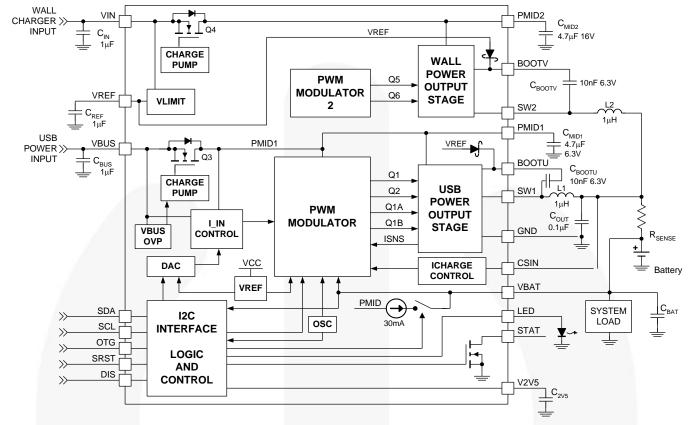


Figure 2. IC and System Block Diagram

**Table 2. Recommended External Components** 

Component	Description	Vendor	Parameter	Тур.	Units
	Charge Currents to 1 A:	Murata: LQM2MPN1R0M	L	1.0	μН
L1, L2:	1 μH, 20%, 1.3 A, 2016	INUIAIA. EQINZIVIFINTROIVI	DCR	85	mΩ
LI, LZ.	Charge Currents Above 1 A:	Murata: LQM2HPN1R0M	L	1.0	μН
	1 μH, 20%, 1.6 A, 2520	Murata. EQMZHFINTROM	DCR	55	mΩ
Сват	10 μF, 20%, 6.3 V, X5R, 0603	Murata: GRM188R60J106M	С	10	μF
$C_{MID1,2}$	4.7 μF, 10%, 16 V, X5R, 0805	Murata: GRM21BR61C475K	С	4.7	μF
C <sub>IN</sub> , C <sub>BUS</sub>	1.0 μF, 10%, 16 V, X5R, 0603	Murata GRM188R61E105K	С	1.0	μF
Своот	10 nF, 10%, 6.3 V, X5R, 0201	Murata GRM033R70J103K	С	10	nF
C <sub>OUT</sub>	0.1 μF, 10%, 6.3 V, X5R, 0201	Murata GRM033R60J104K	С	0.1	μF
$C_{2V5}, C_{REF}$	1μF, 10%, 6.3 V, X5R, 0402	Murata GRM155R60J105M	С	1.0	μF

## **Block Diagrams** (Continued)

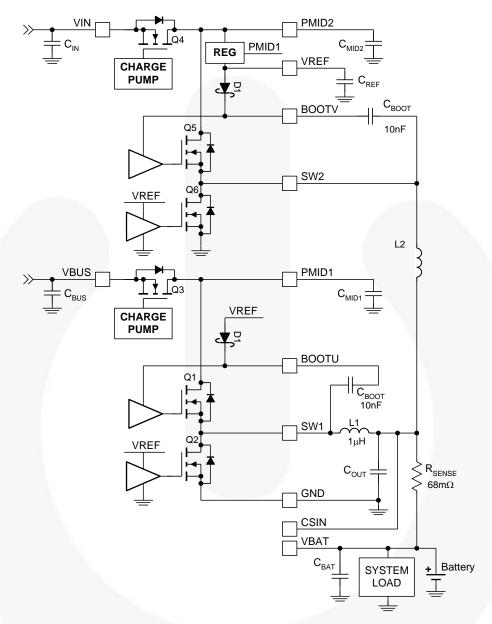


Figure 3. Power Output

## **Pin Configuration**

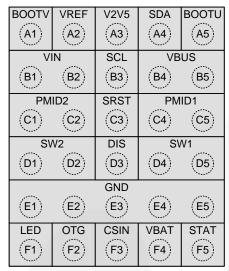


Figure 4. Pin Assignments (Top View)

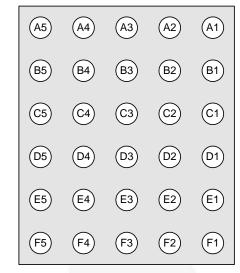


Figure 5. Pin Assignments (Bottom View)

## **Pin Definitions**

Pin#	Name	Description
A1	BOOTV	BOOT. High-side NMOS driver supply. Connect a 10nF capacitor from SW2 to this pin.
A2	VREF	<b>Bias Regulator Output</b> . Connect to a 1 $\mu$ F capacitor to PGND. This pin supplies the internal gate drive and power supply to the IC while charging. Up to 5 mA of current can be provided from this pin to drive external circuits. This pin is active when either $V_{IN}$ or $V_{BUS}$ are above $V_{BAT}$ .
А3	V2V5	<b>2.5 V Regulator</b> . Connect to a 1 $\mu$ F capacitor to PGND. Up to 5 mA can be provided from this pin to drive external circuits. This regulator is powered only when VIN is connected.
A4	SDA	I <sup>2</sup> C Interface Serial Data. This pin should not be left floating.
A5	BOOTU	BOOT. High-side NMOS driver supply. Connect a 10 nF capacitor from SW1 to this pin.
B1, B2	VIN	Charger Input Voltage. Bypass with a minimum of 1 μF, 16 V capacitor to GND.
В3	SCL	I <sup>2</sup> C Interface Serial Clock. This pin should not be left floating.
B4, B5	VBUS	<b>USB Input Voltage</b> . Bypass with a 1 μF, 16 V capacitor to GND.
C1, C2	PMID2	Power Input Voltage for VIN Power Source. Power input to the charger regulator, bypass point for the VIN input current sense, and high-voltage input switch. Bypass with a minimum of 4.7 $\mu$ F, 16 V capacitor to PGND.
C3	SRST	<b>Safety Reset</b> . When LOW, both safety registers are reset to their default values. When HIGH, the safety registers reset when V <sub>BAT</sub> drops below V <sub>SHORT</sub> .
C4, C5	PMID1	<b>Power Input Voltage for VBUS Power Source</b> . Power input to the VBUS switching charger regulator, bypass point for the VBUS input current sense, and high-voltage input switch. Bypass with a minimum of $4.7~\mu\text{F}$ , $6.3~V$ capacitor to PGND.
D1, D2	SW2	Switching Node for VIN Charger. Connect to the output inductor.
D3	DIS	<b>Charge Disable</b> . When this pin is HIGH, charging is disabled and no timers are reset. When LOW, charging is controlled by the I <sup>2</sup> C registers. This pin does not affect the 32-second timer.
D4, D5	SW1	Switching Node for VBUS Charger and OTG Boost. Connect to the output inductor.
E1-E5	GND	<b>Ground</b> . Power return for gate drive and power transistors as well as IC signal ground. The connection from this pin to the bottoms of the C <sub>PMID</sub> capacitors should be as short as possible.
F1	LED	<b>Light Emitting Diode Output</b> . Up to 5 mA current source drive from the active PMID indicates the battery is charging.

Pin #	Name	Description
F2	OTG	<b>On The Go</b> . When unattended charging is indicated, the level on this pin sets the I <sub>BUS</sub> current limit. This pin is also used to put the IC into Boost Mode.
F3	CSIN	<b>Current-Sense Input</b> . Connect to sense resistor in series with the battery. The IC uses this node to sense current into the battery. Bypass this pin with a 0.1 μF capacitor to PGND.
F4	VBAT	<b>Battery Voltage</b> . Connect to the positive (+) terminal of the battery pack. Bypass with a 10 μF capacitor to PGND.
F5	STAT	<b>Status</b> . Open-drain output indicating charge status. The IC pulls this pin LOW when charging is in process.

## **Absolute Maximum Ratings**

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol		Parameter	Min.	Max.	Unit
1.7	\/DLIQ \/-lt	Continuous	-1.4		
$V_{BUS}$	VBUS Voltage	Pulsed, 100 ms Maximum Non-Repetitive	-2.0	20.0	V
V <sub>IN</sub>	VIN Voltage		-2.0	20.0	V
V <sub>BOOTU</sub>	BOOTU Voltage	-0.7	20.0	V	
$V_{BOOTV}$	BOOTV Voltage	OOTV Voltage			V
$V_{PMID1}$	PMID1 Voltage	MID1 Voltage			
V <sub>SW1</sub>	SW1 Voltage	SW1 Voltage			
$V_{PMID2}$	PMID2 Voltage	/	-1.0	20.0	V
V <sub>SW2</sub>	SW2 Voltage		-0.7	12.0	V
Vo	Other Pins		-0.3	6.5 <sup>(1)</sup>	V
$\frac{\text{dV}_{\text{BUS}}}{\text{dt}}$	Maximum Rate of V <sub>BUS</sub> Increas	e Above 5.5 V when IC Enabled		4	V/μs
dV <sub>IN</sub> dt	Maximum Rate of V <sub>IN</sub> Increase Above 9.5 V when IC Enabled			4	V/μs
ESD	Electrostatic Discharge	Human Body Model per JESD22-A114	2	.0	kV
E3D	Protection Level	Charged Device Model per JESD22-C101	1	.5	kV
TJ	Junction Temperature		-40	+150	°C
T <sub>STG</sub>	Storage Temperature		-65	+150	°C
TL	Lead Soldering Temperature, 1	0 Seconds		+260	°C

#### Note

## **Recommended Operating Conditions**

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to absolute maximum ratings.

Symbol	Parameter	Min.	Max.	Units
$V_{BUS}$	VBUS Supply Voltage	4	6	V
$V_{IN}$	VIN Supply Voltage	4.0	9.5	V
T <sub>A</sub>	Ambient Temperature	-30	+85	°C
TJ	Junction Temperature	0	+125	°C

## **Thermal Properties**

Junction-to-ambient thermal resistance is a function of application and board layout. This data is measured with four-layer 2s2p boards in accordance to JEDEC standard JESD51. Special attention must be paid not to exceed junction temperature  $T_{J(max)}$  at a given ambient temperate  $T_A$ .

Symbol	Parameter	Typical	Unit
$\theta_{JA}$	Junction-to-Ambient Thermal Resistance	60	°C/W
$\theta_{JB}$	Junction-to-PCB Thermal Resistance	20	°C/W

Lesser of 6.5 V or V<sub>REF</sub> + 0.3 V.

## **Electrical Specifications**

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for  $T_J$  and  $T_A$ ,  $V_{BUS}$  or  $V_{IN} = 5.0 \text{ V}$ , HZ1, HZ2, OPA\_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8 V. Typical values are for  $T_J = 25^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Power Su	ipplies					•
		PWM Switching, Open Battery, TE=0		33		mA
		PWM Not Switching (V <sub>BAT</sub> > V <sub>OREG</sub> )		3.6		mA
$I_{\text{VBUS}}$	VBUS Current	$0^{\circ}\text{C} < \text{T}_{\text{J}} < 85^{\circ}\text{C}, \text{HZ1} = 1, \text{V}_{\text{BAT}} > \text{V}_{\text{LOWV}}$		350	500	μΑ
		0°C < T <sub>J</sub> < 85°C, HZ1 = 1, V <sub>BAT</sub> < V <sub>LOWV</sub> , 32S Mode		350	500	μA
		PWM Switching, Open Battery, TE=0		33		mA
		PWM Not Switching (V <sub>BAT</sub> >V <sub>OREG</sub> )		2.6		mA
$I_{\text{VIN}}$	VIN Current	$0^{\circ}\text{C} < \text{T}_{\text{J}} < 85^{\circ}\text{C}, \text{HZ2} = 1, \text{V}_{\text{IN}} > \text{V}_{\text{LOWV}}$	1	350	500	μΑ
		0°C < T <sub>J</sub> < 85°C, HZ2 = 1, V <sub>IN</sub> < V <sub>LOWV</sub> , 32S Mode		350	500	μA
	1	0°C < T <sub>J</sub> < 85°C, HZ1=HZ2 = 1 or DIS=1, V <sub>BAT</sub> = 4.2 V			20	μA
I <sub>BAT</sub>	Battery Discharge Current in High-Z Mode	$0^{\circ}\text{C} < \text{T}_{\text{J}} < 85^{\circ}\text{C}, \text{ V}_{\text{BAT}} = 4.2 \text{ V}, \text{ V}_{\text{IN}} = \text{V}_{\text{BUS}} = \text{Open or GND, HZ1=HZ2=1,} \text{SDA} = \text{SCL} = 1.8 \text{ V}, \text{No I}^2\text{C} \text{ Traffic}$			30	μА
Charger \	Voltage Regulation					
	Charge Voltage Range		3.5		4.4	V
V <sub>OREG</sub>	Charge Voltage Accuracy	T <sub>A</sub> = 25°C	-0.5		+0.5	%
		T <sub>J</sub> = 0 to 125°C	-1		+1	%
Charging	<b>Current Regulation</b>					
	Output Charge Current Range	$V_{LOWV} < V_{BAT} < V_{OREG},$ $V_{BUS} > V_{SLP}, R_{SENSE} = 68 \text{ m}\Omega$	550		1500	mA
OCHRG	Charge Current Accuracy	20 mV ≤ V <sub>IREG</sub> ≤ 40 mV	92	97	102	% of Setting
	Across R <sub>SENSE</sub>	V <sub>IREG</sub> > 40 mV	94	97	100	
Weak-Bat	ttery Detection		У		y	
$V_{LOWV}$	Weak-Battery Threshold Accuracy	3.4 ≤ V <sub>LOWV</sub> ≤ 3.7	-5		+5	%
	Weak Battery Deglitch Time	Rising Voltage, 2 mV Overdrive		30		ms
Logic Lev	vels: DIS, SDA, SCL, OTG					•
V <sub>IH</sub>	HIGH-Level Input Voltage		1.05			V
V <sub>IL</sub>	LOW-Level Input Voltage				0.4	V
I <sub>IN</sub>	Input Bias Current	Input Tied to GND or V <sub>BAT</sub>		0.01	1.00	μΑ
Charge T	ermination Detection		, P		TH	
	Termination Current Range	$V_{BAT} > V_{OREG} - V_{RCH}, V_{BUS} > V_{SLP},$ $R_{SENSE} = 68 \text{ m}\Omega$	50		400	mA
I	Tormination Current Assure	[V <sub>CSIN</sub> – V <sub>BAT</sub> ] from 3 mV to 20 mV	-25%		+25%	
I <sub>(TERM)</sub>	Termination Current Accuracy	[V <sub>CSIN</sub> – V <sub>BAT</sub> ] from 20 mV to 40 mV	-5%		+5%	
	Termination Current Deglitch Time	2 mV Overdrive		30		ms

## **Electrical Specifications** (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for  $T_J$  and  $T_A$ ,  $V_{BUS}$  or  $V_{IN} = 5.0 \text{ V}$ , HZ1, HZ2, OPA\_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8V. Typical values are for  $T_J = 25^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
VBUS Inp	ut Power Source Detection					•
V <sub>BUS(MIN)1</sub>	V <sub>BUS</sub> Input Voltage Rising	To Start V <sub>BUS</sub> Validation	4.20	4.30	4.40	V
V <sub>BUS(MIN)2</sub>	Min. V <sub>BUS</sub> to Pass Validation	During V <sub>BUS</sub> Validation Period	4.00	4.08	4.15	V
V <sub>BUS(MIN)3</sub>	Min. V <sub>BUS</sub> During Charge	During Charging	3.64	3.71	3.78	V
tvbus_valid	V <sub>BUS</sub> Validation Time			30		ms
VBUS <sub>LOAD</sub>	V <sub>BUS</sub> Load	V <sub>BUS</sub> = 5 V, Applied at V <sub>BUS</sub> Validation		50		mA
VIN Input	Power Source Detection					•
V <sub>IN(MIN)1</sub>	V <sub>IN</sub> Input Voltage Rising	To Start V <sub>IN</sub> Validation	4.20	4.30	4.40	V
V <sub>IN(MIN)2</sub>	Min. V <sub>IN</sub> to Pass Validation	During V <sub>IN</sub> Validation Period	4.00	4.08	4.15	V
V <sub>IN(MIN)3</sub>	Min. V <sub>IN</sub> During Charge	During Charging	3.64	3.71	3.78	V
t <sub>VBUS_VALID</sub>	V <sub>IN</sub> Validation Time			30		ms
VIN <sub>LOAD</sub>	V <sub>IN</sub> Load	V <sub>IN</sub> = 5 V, Applied at V <sub>IN</sub> Validation	<b>N</b>	50		mA
Input Curi	ent Limit					•
. /	VBUS Input Current-Limit	I <sub>BUS</sub> set to 100 mA	88	93	98	
BUSLIM	Threshold	I <sub>BUS</sub> set to 500 mA	450	475	500	mA
V <sub>2V5</sub> 2.5V I	Linear Regulator					
.,	2.5 V Regulator Output	I <sub>2V5</sub> from 0 to 5 mA, V <sub>IN</sub> > 4.75 V	2.35	2.50	2.65	V
$V_{2V5}$	Current Limit		6	8		mA
V <sub>REF</sub> Bias	Generator					
.,	Bias regulator voltage	$V_{IN} > V_{IN(MIN)}$	3.5		6.0	V
$V_{REF}$	current limit		10	15		mA
Battery Re	echarge Threshold					
.,	Recharge Threshold	Below V <sub>(OREG)</sub>	100	120	150	mV
V <sub>RCH</sub>	Deglitch Time	VBAT falling below V <sub>RCH</sub> threshold	-//	130		ms
STAT Out	put					ı
V <sub>STAT(OL)</sub>	STAT Output LOW	I <sub>STAT</sub> = 10 mA			0.4	V
I <sub>STAT(OH)</sub>	STAT High Leakage Current	V <sub>STAT</sub> = 5 V			1	μA
LED Outp	ut			5/2		•
I <sub>LED(ON)</sub>	LED Output Current Accuracy	$V_{LED}$ from 1.5 to 3.5 V, Max. ( $V_{REF}$ , $V_{BAT}$ ) – $V_{LED}$ > 100 mV	-30		+30	%
I <sub>LED(OFF)</sub>	LED Off-State Leakage Current	V <sub>LED</sub> = 0 V			1	μA
Battery De	etection			•		
I <sub>DETECT</sub>	Battery Detection Current Before Charge Complete (Sink Current) <sup>(2)</sup>	Begins After Termination Detected and VBAT ≤ VOREG −VRCH		-0.45		mA
t <sub>DETECT</sub>	Battery Detection time			262		ms

## **Electrical Specifications** (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for  $T_J$  and  $T_A$ ,  $V_{BUS}$  or  $V_{IN} = 5.0 \text{ V}$ , HZ1, HZ2, OPA\_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8 V. Typical values are for  $T_J = 25^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Sleep Cor	nparator		1	•	•	
V <sub>SLP</sub>	Sleep Mode Entry Threshold, V <sub>BUS</sub> – V <sub>BAT</sub> or V <sub>IN</sub> – V <sub>BAT</sub>	2.3 V ≤ V <sub>BAT</sub> ≤ V <sub>OREG</sub> , V <sub>PWRIN</sub> Falling	0	90	160	mV
	Sleep Mode Exit Hysteresis	$2.3 \text{ V} \leq \text{V}_{BAT} \leq \text{V}_{OREG}$		40		mV
V <sub>SLP_EXIT</sub>	Deglitch Time for V <sub>BUS</sub> Rising Above V <sub>SLP</sub> + V <sub>SLP_EXIT</sub>	Rising Voltage		30		ms
Power Sw	itches (see Figure 3)					
	Q3 On Resistance (VBUS to PMID1)	IBUS <sub>(LIMIT)</sub> ≥ 500 mA		210	300	
	Q1 On Resistance (PMID1 to SW1)			110	225	
D	Q2 On Resistance (SW1 to GND)			130	225	m0
R <sub>DS(ON)</sub>	Q4 On Resistance (VIN to PMID2)			160	225	mΩ
	Q5 On Resistance (PMID2 to SW2)			110	225	
	Q6 On Resistance (SW2 to GND)			190	350	
Charger F	WM Modulator		1	1		
f <sub>SW</sub>	Oscillator Frequency		2.7	3.0	3.3	MHz
D <sub>MAX</sub>	Maximum Duty Cycle				100	%
$D_{MIN}$	Minimum Duty Cycle			0		%
I <sub>SYNC</sub>	Synchronous to Non- Synchronous Current Threshold <sup>(3)</sup>	Low-Side MOSFET Cycle-by-Cycle Current Limit		-120		mA
Boost Mo	de Operation (OPA_MODE = 1,	HZ1 = 0)		•		
V	Donat Output Valtage at VDIIC	2.5 V < V <sub>BAT</sub> < 4.5 V, 0-200 mA Load	4.80	5.05	5.17	\/
$V_{BOOST}$	Boost Output Voltage at VBUS	2.7 V < V <sub>BAT</sub> < 4.5 V, 0-300 mA Load	4.77	5.05	5.17	V
BAT(BOOST)	Boost Mode Quiescent Current	PFM Mode, V <sub>IN</sub> = 3.6 V, I <sub>OUT</sub> = 0	/	300	400	μА
I <sub>LIMPK(BST)</sub>	Q2-Peak Current Limit		1160	1380	1550	mA
V <sub>BAT(MAX)</sub>	Maximum Battery Input for Boost Operation	V <sub>BAT</sub> Rising	4.7			V
, ,	Hysteresis	V <sub>BAT</sub> Falling		125		mV
UVLO <sub>BST</sub>	Minimum Battery Voltage for	While Boost Active		2.42		V
UVLOBST	Boost Operation	To Start Boost Regulator		2.58	2.70	V
VBUS, VII	Load Resistance					
D	VBUS to GND Resistance	Normal Operation	500	1000	1500	Ω
$R_{VBUS}$	עטט נט טואט אפטוצומוונפ	V <sub>BUS</sub> Validation	50	110	175	Ω
	VIN to CND Docists	Normal Operation	500	1000	1500	Ω
$R_{VIN}$	VIN to GND Resistance	V <sub>IN</sub> Validation	50	110	175	Ω

## **Electrical Specifications** (Continued)

Unless otherwise specified: circuit of Figure 1, recommended operating temperature range for  $T_J$  and  $T_A$ ,  $V_{BUS}$  or  $V_{IN} = 5.0 \text{ V}$ , HZ1, HZ2, OPA\_MODE = 0, (Charger Mode). SCL, SDA, OTG = 0 or 1.8 V. Typical values are for  $T_J = 25^{\circ}\text{C}$ .

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Units
Protection	and Timers					
VBUS <sub>OVP</sub>	VBUS Over-Voltage Shutdown	V <sub>BUS</sub> Rising	6.12	6.31	6.50	V
VBUSOVP	Hysteresis	V <sub>BUS</sub> Falling		100		mV
VINI	VIN Over-Voltage Shutdown	V <sub>IN</sub> Rising	9.5	10.0	10.5	V
VIN <sub>OVP</sub>	Hysteresis	V <sub>IN</sub> Falling		100		mV
V	Battery Short-Circuit Threshold	V <sub>BAT</sub> Rising	2.00	2.05	2.10	V
$V_{SHORT}$	Hysteresis	V <sub>BAT</sub> Falling		100		
I <sub>SHORT</sub>	Short-Circuit Current	V <sub>BAT</sub> < V <sub>SHORT</sub>	30	40	50	mA
_	Thermal Shutdown Threshold <sup>(4)</sup>	T <sub>J</sub> Rising		165		00
T <sub>SHUTDWN</sub>	Hysteresis <sup>(4)</sup>	T <sub>J</sub> Falling		10	50	°C
T <sub>CF</sub>	Thermal Regulation Threshold (4)	Charge Current Reduction Begins		120		°C
t <sub>INT</sub>	Detection Interval			2.1		S
t <sub>32SEC</sub>	32-Second Timer <sup>(5)</sup>	32-Second Mode	21.0		31.5	S
t <sub>15MIN</sub>	15-Minute Timer	15-Minute Mode	12.0	13.5	15.0	min
$\Delta t_{LF}$	Low Frequency Timer Accuracy	Charger Inactive	-25		25	%

#### Notes:

- 2. Refers to negative inductor current. At lower battery charging current, of about 20 mA, non-synchronous switching operation commences.
- 3. Q2 and Q6 always turn on for »60 ns and then turn off if the current is below I<sub>SYNC</sub>.
- 4. Guaranteed by design.
- 5. This tolerance applies to all timers on the IC, including soft-start and deglitching timers.

## I<sup>2</sup>C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Uni	
		Standard Mode			100		
	COL Olask Francisco	Fast Mode			400	1.11-	
f <sub>SCL</sub>	SCL Clock Frequency	High-Speed Mode, C <sub>B</sub> ≤ 100 pF			3400	kHz	
		High-Speed Mode, C <sub>B</sub> ≤ 400 pF			1700	İ	
	Bus-Free Time between STOP	Standard Mode		4.7			
t <sub>BUF</sub>	and START Conditions	Fast Mode		1.3		μS	
		Standard Mode		4		μS	
t <sub>HD;STA</sub>	START or Repeated START Hold Time	Fast Mode		600		ns	
	Tiola Time	High-Speed Mode		160		ns	
	7/2	Standard Mode		4.7		μS	
	001 1 014 5	Fast Mode		1.3		μ	
$t_{LOW}$	SCL LOW Period	High-Speed Mode, C <sub>B</sub> ≤ 100 pF		160		ns	
	7.	High-Speed Mode, C <sub>B</sub> ≤ 400 pF		320		ns	
- 7		Standard Mode		4		μ	
. /		Fast Mode		600		ns	
t <sub>HIGH</sub>	SCL HIGH Period	High-Speed Mode, C <sub>B</sub> ≤ 100 pF		60		ns	
		High-Speed Mode, C <sub>B</sub> ≤ 400 pF		120		n	
	Repeated START Setup Time	Standard Mode		4.7		μ	
t <sub>SU;STA</sub>		Fast Mode		600		n	
		High-Speed Mode		160		n	
		Standard Mode		250			
t <sub>SU;DAT</sub>	Data Setup Time	Fast Mode		100		n	
		High-Speed Mode		10			
		Standard Mode	0		3.45	μ	
	Data Hald Time	Fast Mode	0		900	n	
t <sub>HD;DAT</sub>	Data Hold Time	High-Speed Mode, C <sub>B</sub> ≤ 100 pF	0		70	n	
		High-Speed Mode, C <sub>B</sub> ≤ 400 pF	0		150	n	
		Standard Mode	20+0	0.1C <sub>B</sub>	1000		
	001 B: T	Fast Mode	20+0	20+0.1C <sub>B</sub>			
t <sub>RCL</sub>	SCL Rise Time	High-Speed Mode, C <sub>B</sub> ≤ 100 pF		10	80	n	
		High-Speed Mode, C <sub>B</sub> ≤ 400 pF		20	160		
		Standard Mode	20+0	).1C <sub>B</sub>	300		
	CCL Fall Time	Fast Mode	20+0	).1C <sub>B</sub>	300		
t <sub>FCL</sub>	SCL Fall Time	High-Speed Mode, C <sub>B</sub> ≤ 100 pF		10	40	n	
		High-Speed Mode, C <sub>B</sub> ≤ 400 pF		20	80		
	SDA Rise Time	Standard Mode	20+0.1C <sub>B</sub>		1000		
t <sub>RDA</sub>	Rise Time of SCL after a	Fast Mode	20+0	).1C <sub>B</sub>	300		
t <sub>RCL1</sub>	Repeated START Condition	High-Speed Mode, C <sub>B</sub> ≤ 100 pF		10	80	n	
	and after ACK Bit	High-Speed Mode, C <sub>B</sub> ≤ 400 pF		20	160		

## I<sup>2</sup>C Timing Specifications

Guaranteed by design.

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
		Standard Mode	20+0.1C <sub>B</sub>		300	
	SDA Fall Time	Fast Mode	20+0.1C <sub>B</sub>		300	
t <sub>FDA</sub>	SDA Fall Time	High-Speed Mode, C <sub>B</sub> ≤ 100 pF		10	80	ns
		High-Speed Mode, C <sub>B</sub> ≤ 400 pF		20	160	
		Standard Mode		4		μS
t <sub>SU;STO</sub>	Stop Condition Setup Time	Fast Mode		600		ns
		High-Speed Mode		160		ns
Св	Capacitive Load for SDA, SCL				400	pF

## **Timing Diagrams**

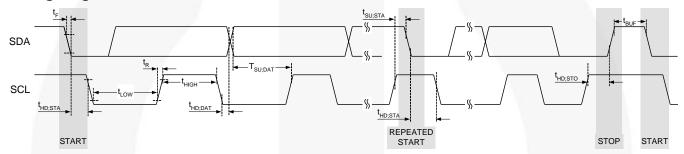


Figure 6. I<sup>2</sup>C Interface Timing for Fast and Slow Modes

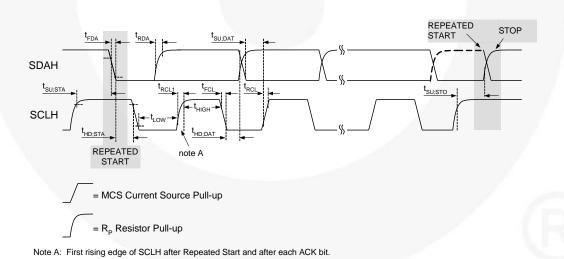
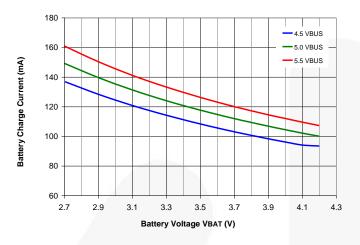


Figure 7. I<sup>2</sup>C Interface Timing for High-Speed Mode

## **VBUS Charge Mode Typical Characteristics**

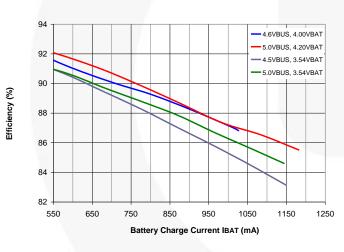
Unless otherwise specified, circuit of Figure 1, V<sub>OREG</sub>=4.2 V, V<sub>BUS</sub>=5.0 V, and T<sub>A</sub>=25°C.



1,000 4.5 VBUS 5.0 VBUS 900 Battery Charge Current (mA) 800 700 600 500 400 2.7 2.9 3.1 3.3 3.5 3.7 3.9 4.1 4.3 Battery Voltage VBAT (V)

Figure 8. Battery Charge Current vs.  $V_{\text{BUS}}$  with  $I_{\text{INLIM}} = 100 \text{ mA}$ 

Figure 9. Battery Charge Current vs.  $V_{BUS}$  with  $I_{INLIM}$ =500 mA



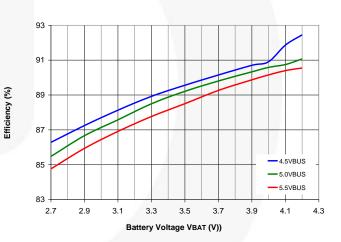


Figure 10. Charger Efficiency, No I<sub>INLIM</sub>, I<sub>OCHARGE</sub>=1250 mA

Figure 11. Charger Efficiency vs.  $V_{\text{BUS}}$ ,  $I_{\text{INLIM}}$ =500 mA

## **VBUS Charge Mode Typical Characteristics**

Unless otherwise specified, circuit of Figure 1, V<sub>OREG</sub>=4.2 V, V<sub>BUS</sub>=5.0 V, and T<sub>A</sub>=25°C.

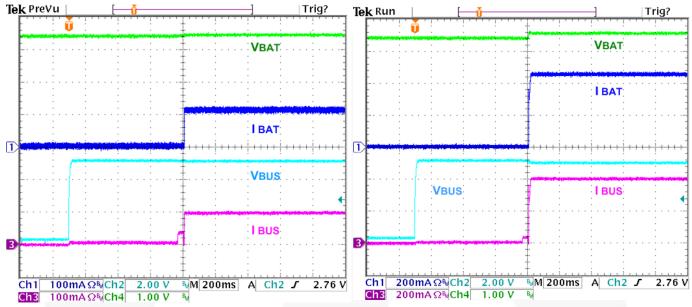


Figure 12. Auto-Charge Startup at  $V_{BUS}$  Plug-in,  $I_{INLIM}$ =100 mA, OTG=1,  $V_{BAT}$ =3.4 V

Figure 13. Auto-Charge Startup at  $V_{BUS}$  Plug-in,  $I_{INLIM}$ =500 mA, OTG=1,  $V_{BAT}$ =3.4 V

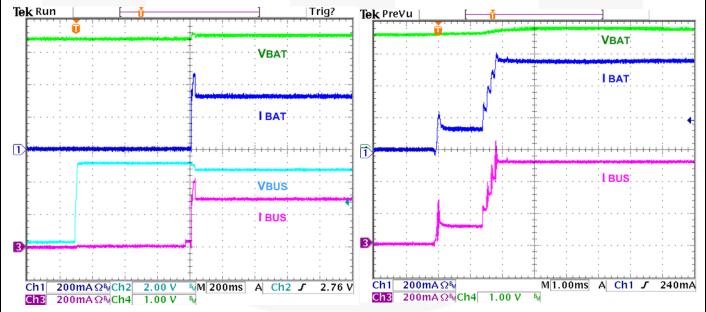


Figure 14. AutoCharge Startup with 300 mA Limited Charger / Adaptor,  $I_{\rm INLIM}$ =500 mA, OTG=1,  $V_{\rm BAT}$ =3.4 V

Figure 15. Charger Startup with HZ\_MODE Bit Reset,  $I_{\text{INLIM}} \!\!=\!\! 500$  mA,  $I_{\text{OCHARGE}} \!\!=\!\! 950$  mA,  $V_{\text{OREG}} \!\!=\!\! 4.2$  V,  $V_{\text{BAT}} \!\!=\!\! 3.6$  V

## **VBUS Charge Mode Typical Characteristics**

Unless otherwise specified, circuit of Figure 1, V<sub>OREG</sub>=4.2 V, V<sub>BUS</sub>=5.0 V, and T<sub>A</sub>=25°C.

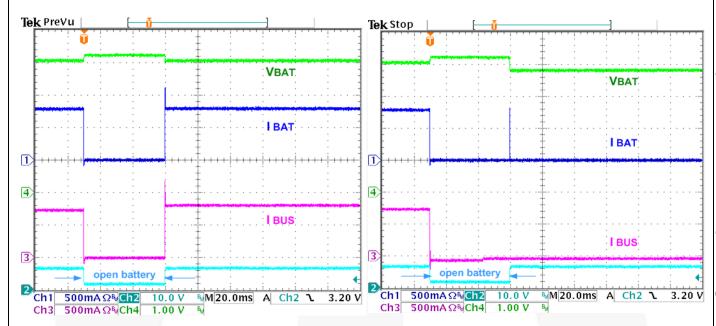


Figure 16. Battery Removal / Insertion during Charging,  $V_{\text{BAT}} \! = \! 3.9 \text{ V}, I_{\text{OCHARGE}} \! = \! 950 \text{ mA}, \text{No } I_{\text{INLIM}}, \text{TE=0}$ 

Figure 17. Battery Removal / Insertion during Charging, VBAT=3.9 V, IOCHARGE=950 mA, No INLIM, TE=1

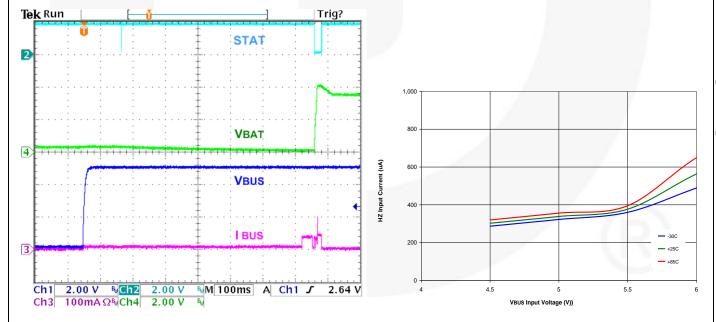
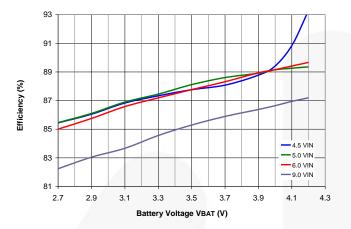


Figure 18. No Battery at V<sub>BUS</sub> Power-up

Figure 19. VBUS Current in High-Impedance Mode with Battery Open

## **VIN Charger Characteristics**

Unless otherwise specified, circuit of Figure 1,  $V_{OREG} = 4.2 \text{ V}$ ,  $V_{IN} = 5.0 \text{ V}$ , and  $T_A = 25 ^{\circ}\text{C}$ .



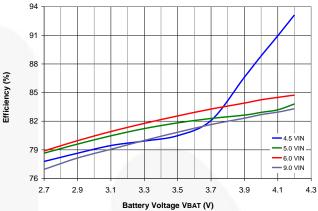
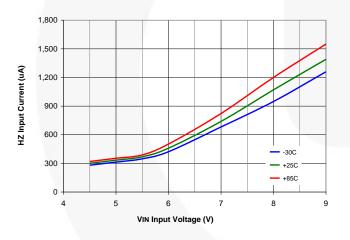


Figure 20. Charger Efficiency, I<sub>OCHARGE</sub>=950 mA

Figure 21. Charger Efficiency, I<sub>OCHARGE</sub>=1550 mA



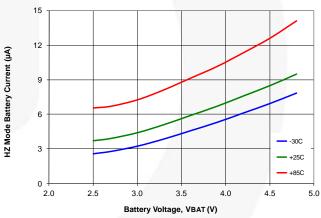


Figure 22. V<sub>IN</sub> Current in High-Impedance Mode, V<sub>BAT</sub>=3.6 V

Figure 23. Battery Current in High-Impedance Mode, VBUS=Open, V<sub>IN</sub>=Open

## **VIN Charger Characteristics**

Unless otherwise specified, circuit of Figure 1,  $V_{OREG} = 4.2 \text{ V}$ ,  $V_{IN} = 5.0 \text{ V}$ , and  $T_A = 25 ^{\circ}\text{C}$ .

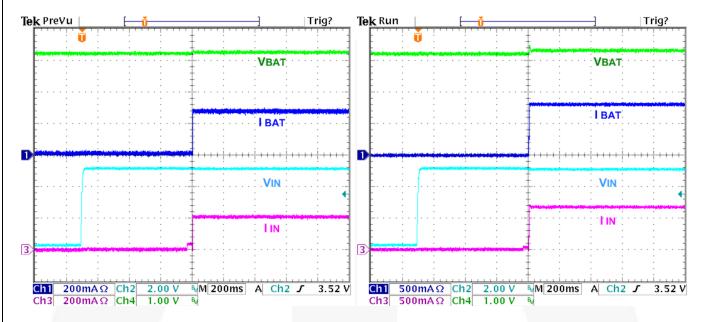


Figure 24. Auto-Charge Startup at  $V_{IN}$  Plug-in,  $V_{BAT}$ =3.2 V,  $IO_LEVELV$  = 1

Figure 25. Auto-Charge Startup at  $V_{IN}$  Plug-in,  $V_{BAT}$ =3.2 V,  $I_{OCHARGE}$ =950 mA

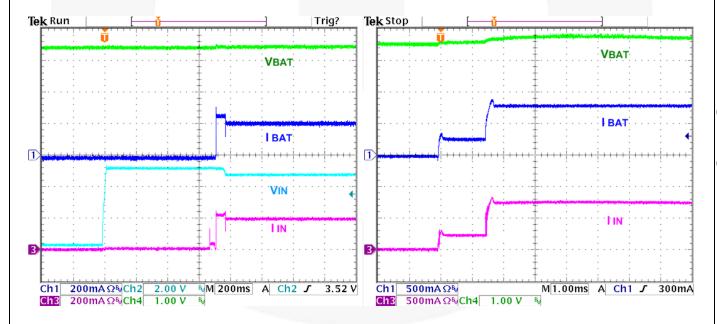


Figure 26. Auto-Charge Startup with 200 mA Limited Charger / Adaptor,  $V_{BAT}$ =3.4 V

Figure 27. Charger Startup with HZ\_MODE Bit Reset, I<sub>OCHARGE</sub>=950 mA, V<sub>OREG</sub>=4.2 V, V<sub>BAT</sub>=3.6 V

## **VIN Charger Characteristics**

Unless otherwise specified, circuit of Figure 1,  $V_{OREG} = 4.2 \text{ V}$ ,  $V_{IN} = 5.0 \text{ V}$ , and  $T_A = 25 ^{\circ}\text{C}$ .

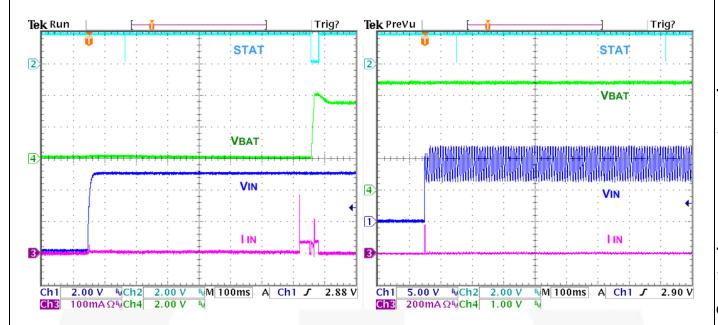


Figure 28. No Battery at VIN Power-up

Figure 29. Non-Compliant Charger Rejection,  $V_{BAT}$ =3.4 V

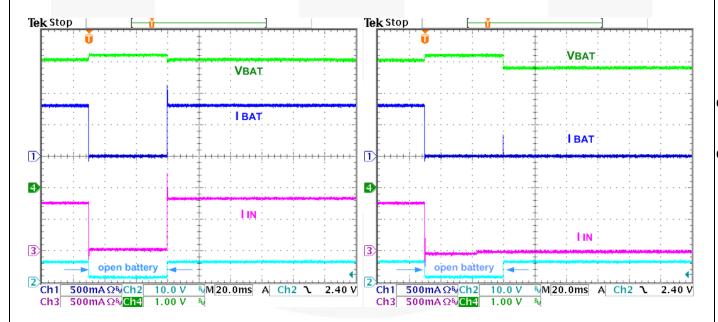
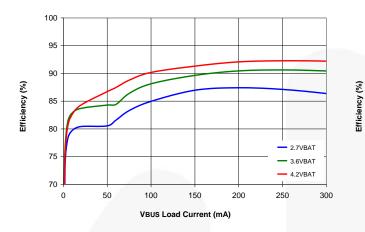


Figure 30. Battery Removal / Insertion During Charging,  $V_{BAT}$ =3.9 V,  $I_{OCHARGE}$ =950 mA, TE=0

Figure 31. Battery Removal / Insertion During Charging,  $V_{BAT}$ =3.9 V,  $I_{OCHARGE}$ =950 mA, TE=1

## **Boost Mode Typical Characteristics**

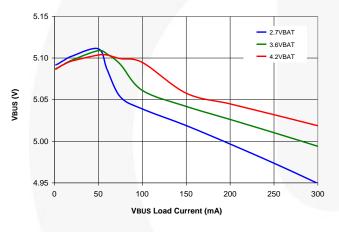
Unless otherwise specified, using the circuit of Figure 1, V<sub>BAT</sub>=3.6 V, T<sub>A</sub>=25°C.



100 85 80 -10C, 3.6VBAT 75 +25C, 3.6VBAT +85C, 3.6VBAT 70 50 100 200 300 0 150 250 VBUS Load Current (mA)

Figure 32. Efficiency vs. VBAT





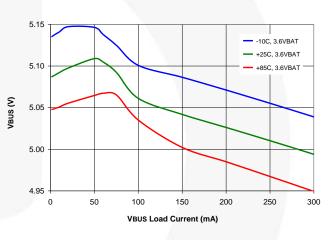
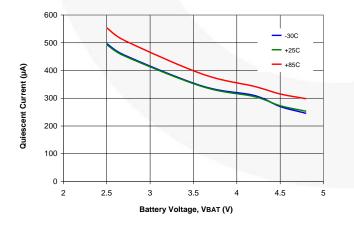


Figure 34. Output Regulation vs. VBAT

Figure 35. Output Regulation Over Temperature



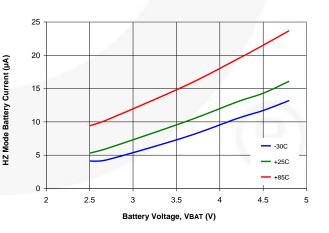


Figure 36. Quiescent Current

Figure 37. High-Impedance Mode Battery Current

## **Boost Mode Typical Characteristics**

Unless otherwise specified, using the circuit of Figure 1, V<sub>BAT</sub>=3.6 V, T<sub>A</sub>=25°C.

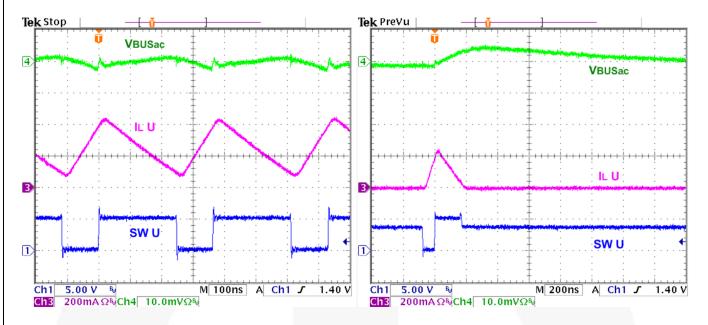


Figure 38. Boost PWM Waveform

Figure 39. Boost PFM Waveform

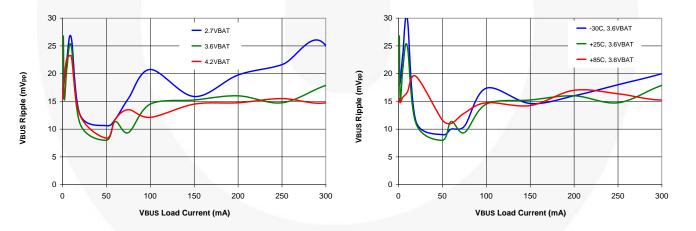


Figure 40. Output Ripple vs. V<sub>BAT</sub>

Figure 41. Output Ripple vs. Temperature

## **Boost Mode Typical Characteristics**

Unless otherwise specified, using the circuit of Figure 1, V<sub>BAT</sub>=3.6 V, T<sub>A</sub>=25°C.

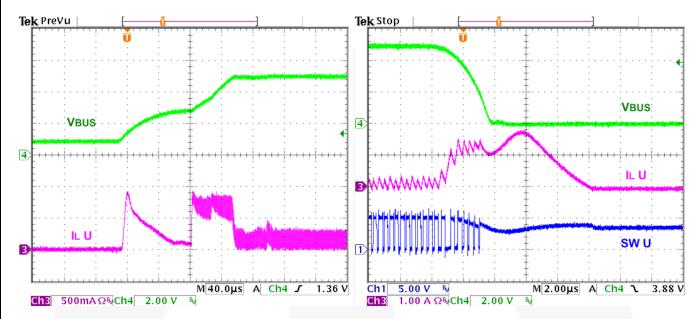


Figure 42. Startup, 3.6  $V_{BAT}$ , 50  $\Omega$  Load, Additional 10  $\mu F$ , X5R Across VBUS

Figure 43.  $V_{\text{BUS}}$  Fault Response, 3.6  $V_{\text{BAT}}$ 

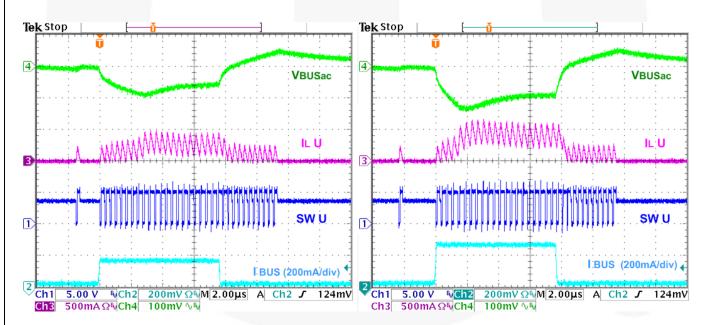


Figure 44. Load Transient, 5-155-5 mA, t<sub>R</sub>=t<sub>F</sub>=100 ns

Figure 45. Load Transient, 5-255-5 mA,  $t_R$ = $t_F$ =100 ns

## **Circuit Description / Overview**

When charging batteries with a current-limited input source, such as USB, a switching charger's high efficiency over a wide range of output voltages minimizes charging time.

The FAN54300 combines two highly integrated synchronous buck regulators for charging from two separate power sources. The IC also includes a synchronous boost regulator, which can supply 5 V to USB On-The-Go (OTG) peripherals. The regulator employs synchronous rectification for both the charger and boost regulators to maintain high efficiency over a wide range of battery voltages and charge states.

In addition to its USB (VBUS) input, the FAN54300 allows a second power source (VIN) to be used for charging. This input source is typically a "wall wart" and can be up to 9.5 V input.

The FAN54300 has three operating modes:

#### Charge Mode:

Charges a single-cell Li-lon or Li-polymer battery.

#### Boost Mode

Provides 5 V power to USB-OTG with an integrated synchronous rectification boost regulator using the battery as input.

#### High-Impedance Mode:

Both the boost and charging circuits are off in this mode. Current flow from PWRIN (the charging power source) to the battery, or from the battery to PWRIN, are blocked in this mode. This mode consumes very little current from PWRIN or the battery.

When the IC is charging the battery from VIN, the boost regulator may be simultaneously enabled to supply 5 V for OTG peripherals.

## **Charge Mode**

In Charge Mode, FAN54300 employs five regulation loops:

- VBUS input current: Limits the amount of current drawn from VBUS. This current is sensed internally and can be programmed through the I<sup>2</sup>C interface
- Charging current: Limits the maximum charging current. This current is sensed using an external R<sub>SENSE</sub> resistor.
- 3. Charge voltage: The regulator is restricted from exceeding this voltage. As the internal battery voltage rises, the battery's internal impedance and R<sub>SENSE</sub> works in conjunction with the charge voltage regulation to decrease the amount of current flowing to the battery. Battery charging is completed when the voltage across R<sub>SENSE</sub> drops below the I<sub>TERM</sub> threshold.
- Temperature: If the IC's junction temperature reaches 120°C, charge current is continuously reduced until the IC's temperature stabilizes at 120°C.
- An additional loop limits the amount of drop on VBUS or VIN to a programmable voltage (V<sub>SP</sub>) to accommodate current-limited wall chargers.

## **Input Source Selection**

The FAN54300 selects the power source (PWRIN) for charging according to the following criteria.

**Table 3. PWRIN: Charging Power Input Source Selection** 

V <sub>IN</sub>	V <sub>BUS</sub>	PWRIN
VALID	INVALID	V <sub>IN</sub>
INVALID	VALID	$V_{BUS}$
VALID	VALID	V <sub>IN</sub>

If charging is in progress with  $V_{BUS}$  and  $V_{IN}$  becomes valid, charging from VBUS stops and charging continues from  $V_{IN}$ . Charging stops if HZ\_VIN is set when  $V_{IN}$  becomes valid while charging with  $V_{BUS}$ .

If VIN and VBUS are both connected and  $t_{15MIN}$  expires, both CE# bits are set. To reinitiate  $t_{15MIN}$  charging (autocharge) with a weak battery, both power sources must be unplugged, then a valid power source plugged in. If only one of the two connected sources are removed then connected with a weak battery, both CE# bits remain set.

### **Fault Reporting and Register Reset**

All faults that occur during charging or boost are reported only in the STATUS register (R0) associated with the active charging source at the time of the fault. Any register reset that occurs due to t<sub>32SEC</sub> overflow resets only the registers associated with the active charging source.

For example: Assume the IC is charging in 32-Second Mode with  $V_{\text{IN}}$  as a source. The processor stops setting TMR\_RST, so  $t_{32\text{SEC}}$  expires. The IC then resets only the \_V registers and goes into 15-Minute Mode charging with  $V_{\text{IN}}$ . A timer fault is enunciated, but reported in the CONTROLO\_V register. CONTROLO\_U is unaffected by this event. When the  $t_{15\text{MIN}}$  timer expires, the IC sets the CE#\_V bit, but leaves the CE#\_U bit unchanged.

## **Battery Charging Curve**

If the battery voltage is below  $V_{SHORT}$ , a linear current source "pre-charges" the battery until  $V_{BAT}$  reaches  $V_{SHORT}$ . The PWM charging circuits are then started and the battery is charged with a constant current if sufficient input power is available. The current slew rate is limited to prevent overshoot.

The FAN54300 is designed to work with a current-limited input source at PWRIN. During the current regulation phase of charging, PWRIN current limitations or the programmed charging current limit the amount of current available to charge the battery and power the system. The effect of input power limitations on I<sub>CHARGE</sub> can be seen in Figure 47.

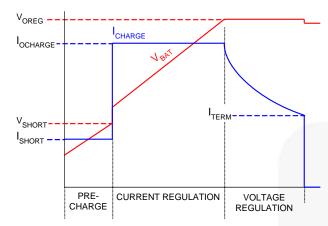


Figure 46. Charge Curve when PWRIN Limitations Don't Limit I<sub>CHARGE</sub>

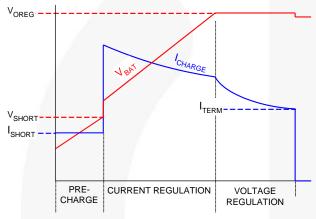


Figure 47. Charge Curve when PWRIN Limits I<sub>CHARGE</sub>

PWRIN limitations are controlled either by:

- IBUSLIM: These bits set the maximum amount of current that the charger draws from VBUS; OR
- SP\_CHARGER: For power-limited chargers, the FAN54300 limits current draw when the charging source drops to the voltage programmed by the SP\_CHARGER bits. This allows "travel adapters" to be accommodated without host software overhead. The SP\_CHARGER control loop applies to both VIN and VBUS.

Assuming  $V_{OREG}$  is programmed to the cell's fully charged "float" voltage, the current the battery accepts with the PWM regulator limiting its output (sensed at VBAT) to VOREG declines and the charger enters the voltage regulation phase of charging. When the current declines to the programmed  $I_{TERM}$  value, the charge cycle is complete. Charge current termination can be disabled by resetting the TE bit.

## **Charger Programmability**

Throughout this document, any parameter that ends in "U" applies when charging from  $V_{BUS}$  and any parameter ending in "V" applies when charging from  $V_{IN}$ . Parameters set with slave address D6 are applied when charging from  $V_{BUS}$ . Parameters set with slave address D4 are applied when charging from  $V_{IN}$ .

The following charging and input power control parameters can be programmed by the host through I<sup>2</sup>C.

**Table 4. Programmable Charging Parameters** 

Parameter	Charging Source	Name	Register
Output Voltage Regulation	Either	OREG	REG2[7:2]
Battery Charging	$V_{BUS}$	ICHGU	REG4[6:4]
Current Limit	V <sub>IN</sub>	ICHGV	REG4[6:3]
Input Current Limit	$V_{BUS}$	IBUSLIM	REG1[7:6]
Charge Termination Limit	Either	ITERM	REG4[2:0]
Special Charger Minimum Voltage	Either	VSP	REG5[2:0]

The charger output or "float" voltage can be programmed by the OREG bits from 3.5 V to 4.44 V in 20 mV increments.

Table 5. OREG Bits ( REG2 [7:2] ) vs. Charger  $V_{\text{OUT}}$  ( $V_{\text{OREG}}$ ) Float Voltage

(V <sub>OREG</sub> ) Float Voltage											
Decimal	Hex	VOREG	Decimal	Hex	VOREG						
0	00	3.50	32	20	4.14						
1	01	3.52	33	21	4.16						
2	02	3.54	34	22	4.18						
3	03	3.56	35	23	4.20						
4	04	3.58	36	24	4.22						
5	05	3.60	37	25	4.24						
6	06	3.62	38	26	4.26						
7	07	3.64	39	27	4.28						
8	08	3.66	40	28	4.30						
9	09	3.68	41	29	4.32						
10	0A	3.70	42	2A	4.34						
11	0B	3.72	43	2B	4.36						
12	0C	3.74	44	2C	4.38						
13	0D	3.76	45	2D	4.40						
14	0E	3.78	46	2E	4.42						
15	0F	3.80	47	2F	4.44						
16	10	3.82	48	30	4.44						
17	11	3.84	49	31	4.44						
18	12	3.86	50	32	4.44						
19	13	3.88	51	33	4.44						
20	14	3.90	52	34	4.44						
21	15	3.92	53	35	4.44						
22	16	3.94	54	36	4.44						
23	17	3.96	55	37	4.44						
24	18	3.98	56	38	4.44						
25	19	4.00	57	39	4.44						
26	1A	4.02	58	ЗА	4.44						
27	1B	4.04	59	3B	4.44						
28	1C	4.06	60	3C	4.44						
29	1D	4.08	61	3D	4.44						
30	1E	4.10	62	3E	4.44						
31	1F	4.12	63	3F	4.44						

#### Note:

All register default settings are noted by **bold typeface**.

## **Charge Initiation**

A new charge cycle begins when one of the following occurs:

- The battery voltage falls below V<sub>OREG</sub> V<sub>RCH</sub>
- A power source is connected (PWRIN POR) and battery voltage is below the weak-battery threshold (V<sub>LOWV</sub>).
- CE# and HZ\_MODE are both cleared, after having been set, and a power source is connected.

### **Charge Current Limit**

The default charge current is limited by the IOLEVEL bit ( REG5[5] ). When this bit is set (default), charge current is limited to 325 mA (22.1 mV across  $R_{\text{SENSE}}$ ) and the ICHG bits are ignored. Resetting IOLEVEL allows the ICHG bits to control the battery charge current limit.

Any attempt to write a value higher than 10 (0AH) results in a value of 10 (0AH) written to the ICHGV bits (see Table 24).

### **Charge Termination Current Limit**

Current charge termination is enabled when TE ( REG1[3] ) = 1. The current level is control by the ITERM bits ( REG4[2:0].

## **PWM Controller in Charge Mode**

The IC uses a current-mode PWM controller to regulate the output voltage and battery charge currents. A cycle-by-cycle current limit of nominally 2.3 A, sensed through Q1, is used to terminate  $t_{\text{ON}}$ . The synchronous rectifier, Q2, also has a current limit that turns off Q2 at 160mA to prevent current flow from the battery.

When the charge current drops below ~20 mA; the IC runs in Asynchronous Mode, which prevents reverse current from pumping up the input source.

#### **Safety Timer** (see Figure 52)

At the beginning of the charging process, the IC starts the 15-minute timer ( $t_{15\text{MIN}}$ ). When this timer expires, charging is terminated and the CE# bit is set. Writing to any register through I²C stops the  $t_{15\text{MIN}}$  timer, which, in turn, starts a 32-second timer ( $t_{32\text{SEC}}$ ). Setting the TMR\_RST bit (REG0[1]) resets the  $t_{32\text{SEC}}$  timer. If the  $t_{32\text{SEC}}$  timer times out, all registers (except SAFETY) are set to their default values, a Timer Fault (110) is reported in the fault register, and charging resumes using the default values with the  $t_{15\text{MIN}}$  timer running.

Since there is only one  $t_{32SEC}$  timer on the IC, writing to either TMR\_RST bit in either CONTROL0\_U or CONTROL0\_V resets the timer. The  $t_{32SEC}$  timer starts with an I $^2$ C WRITE to either slave address. Timer faults are reported in both U and V registers. A  $t_{32SEC}$  fault resets U and V registers 1 – 5.

Normally, charging is controlled by the host with the  $t_{32SEC}$  timer running to ensure that the host is active. Charging with the  $t_{15MIN}$  timer running is used for charging that is unattended by the host, which would occur when  $V_{BAT}$  is insufficient to power the host processor. If the 15-minute timer expires, the IC turns off the charger and indicates a timer fault (110) on the FAULT bits ( REG0[2:0] ). This prevents overcharge if the host fails to reset the  $t_{32SEC}$  timer. The CE# bit is set in the registers where the power sources are connected. For example, if VIN and VBUS are both connected when the  $t_{15MIN}$  timer expires, CE#\_V and CE\_U are both set.

#### **Reset Bit**

Setting the RESET bit ( Reg4[7] ) resets all registers for the slave address used to set the RESET bit. When the RESET bit is set, the  $t_{\rm 32SEC}$  timer is reset and stopped, charging stops and the IC goes to Charge Configuration Mode (see Figure 50). If  $V_{\rm BAT}$  <  $V_{\rm OREG}$ , charging begins in 15-Minute Mode 262 ms after the RESET bit is set.

## PWRIN Validation, Notification, and Non-Compliant Power Source Rejection

Whenever either VBUS\_CON or VIN\_CON bits have been set, the STAT pin pulses to notify the host processor of a change in status on the input power supply.

Before attempting to charge, the IC attempts to validate its input source by loading the appropriate source with 110  $\Omega$  to ensure that the source stays between 4.4 V and VIN $_{\text{OVP}}$  for 32 ms. If the input source fails validation, STAT enunciates a fault and the fault bits are set according to the condition of the input source (OVP or poor input source). The PWRIN validation sequence always occurs before charging is initiated or re-initiated (for example, after a PWRIN OVP fault, a  $V_{\text{RCH}}$  recharge initiation, or resetting the HZ bit). The 32 ms validation time ensures that unfiltered 50/60 Hz chargers and other non-compliant chargers are rejected.

## 2.5 V Regulator Operation

When the VIN\_CON bit is set, indicating that the VIN power source has been plugged in, the V2V5 regulator is enabled.

### **USB-Friendly Boot Sequence** (see Figure 48)

At PWRIN POR, when the battery voltage is above the weak-battery threshold ( $V_{LOW}$ ), the IC goes into Charge Configuration Mode unless the  $t_{32SEC}$  timer is enabled by an I<sup>2</sup>C write. In that case, the IC begins to charge with the existing register settings.

If  $V_{BAT} < V_{LOW}$ , the IC goes into Charge Configuration Mode if the  $t_{32SEC}$  timer is not enabled. If  $V_{BAT} < V_{OREG}$ , the registers reset and charging begins in 15-Minute Mode. During 15-Minute Mode, the charger uses an input current limit controlled by the OTG pin when charging from VBUS (100mA if OTG is LOW and 500mA if OTG is HIGH).

Even if charging from VIN, the charging current is limited to 325 mA (22.14 mV across  $68m\Omega$ ) after the registers are reset. This feature can revive a cell whose voltage is too low for reliable host operation until the battery has sufficient charge for the host to boot up and set charge parameters. Charging continues in the absence of host communication even after the battery has reached V<sub>OREG</sub>, with a default value of 3.54 V, and the charger remains active until  $t_{15MIN}$  times out.

Once the host processor begins writing to the IC, charging parameters are set by the host, which must continually reset the t<sub>32SEC</sub> timer to continue charging using programmed charging parameters. If t<sub>32SEC</sub> times out, the register defaults are loaded, the FAULT bits are set to 110, STAT is pulsed, and charging continues with default charge parameters.

At PWRIN POR, if  $V_{BAT} < V_{LOW}$  and HZ or CE# were set previously, the IC goes into HZ state, which causes the registers to reset, clearing the HZ and CE# bits when  $t_{32SEC}$  expires and beginning  $t_{15MIN}$  charging unless the host processor sets the TMR\_RST bit.

## **VBUS Current Limiting**

To minimize charging time without overloading VBUS's current limitations, the IC's VBUS current limit can be programmed with the IBUSLIM bits ( REG1[7:6] ).

The OTG pin establishes the VBUS current limit during 15-Minute Mode charging.

## **Operational Flow Charts**

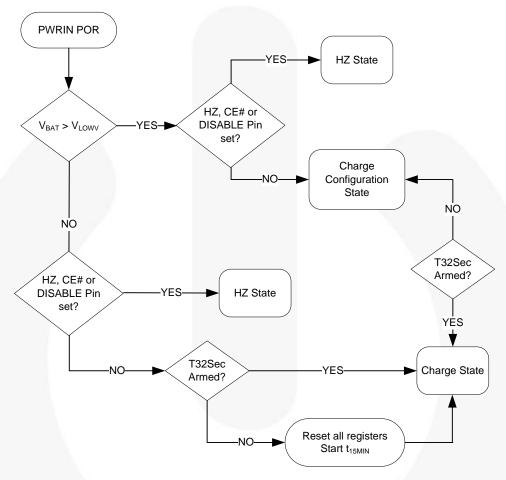
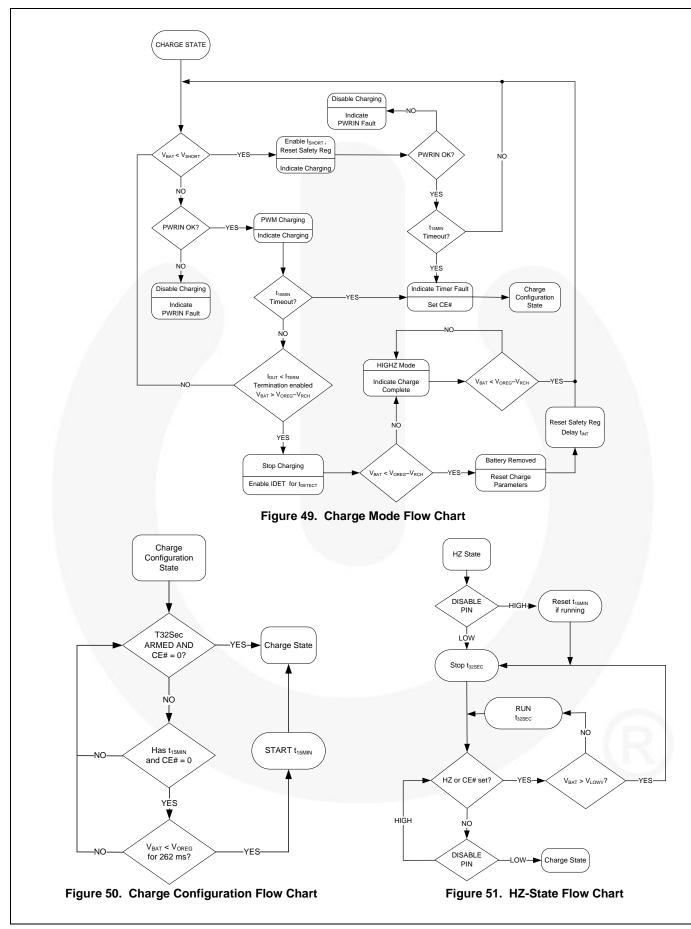


Figure 48. Charger PWRIN POR Flow Chart



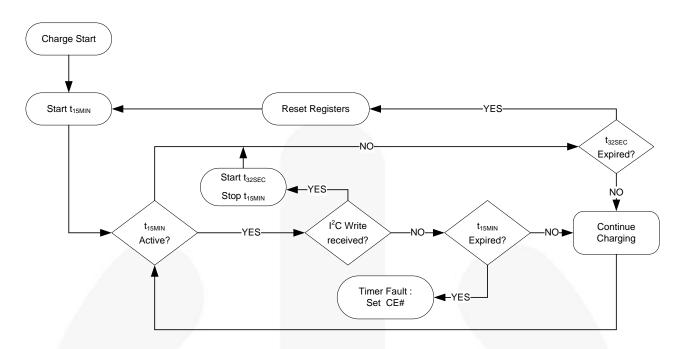


Figure 52. Timer Flow Chart

## **Special Charger**

The IC limits input current in case a current-limited charger is supplying  $V_{\text{BUS}}$  or  $V_{\text{IN}}$ . The IC slowly increases the charging current until either:

- I<sub>BUSLIM</sub> or I<sub>CHARGE</sub> is reached; or
- V<sub>PWRIN</sub> = V<sub>SP</sub> where V<sub>PWRIN</sub> is the selected input power source (see Table 4).

If  $V_{PWRIN}$  collapses to  $V_{SP}$  when current is ramping up, the IC charges with an input current that keeps  $V_{PWRIN} = V_{SP}$ . When the  $V_{SP}$  control loop is limiting the charge current, the SP bit ( REG5[4] ) is set.  $V_{SP}$  default value is 4.53 V, but it can be programmed by REG5[2:0].

### Safety Settings

A SAFETY register ( REG6 ) prevents the values in OREG (REG2[7:2] ) and ICHG ( REG4[6:3] ) from exceeding the values of the VSAFE and ISAFE values.

After  $V_{BAT}$  rises above  $V_{SHORT}$ , the SAFETY register is loaded with its default value and may be written only before any other register is written. After writing to any other register, the SAFETY register is locked until  $V_{BAT}$  falls below  $V_{SHORT}$ . The SAFETY register is reset whenever the SRST pin is LOW.

ISAFE and VSAFE establish values that limit the maximum values of ICHG and OREG used by the control logic. If the host attempts to write a value higher than VSAFE or ISAFE to OREG or ICHG, respectively; the VSAFE, ISAFE value appears as the OREG, ICHG register value, respectively.

For the SAFETY\_U register, any attempt to write an ISAFE value higher than 10 (0AH) results in a value of 10 being written to the ISAFE bits. See Table 21 for VSAFE values and Table 20 and Table 26 for ISAFE values.

### **Thermal Regulation and Protection**

When the IC's junction temperature reaches  $T_{CF}$  (about 120°C) the charger reduces its output current to prevent overheating. If the temperature continues to increase, the current is reduced to 0 when the junction is 10°C above  $T_{CF}$ . If the temperature increases beyond  $T_{SHUTDOWN}$ , charging is suspended, the FAULT bits are set to 101, and SAT is pulsed. In Suspend Mode, all timers stop and the state of the IC's logic is preserved. Charging resumes after the die cools to about 10°C below  $T_{SHUTDOWN}$ .

## **Charge Mode Input Supply Protection Sleep Mode**

When  $V_{BUS}$  and  $V_{IN}$  are both below  $V_{BAT}$ , the IC enters Sleep Mode. To prevent the battery from discharging into VBUS, reverse current is prevented by body switching Q1 when PMID1 falls below  $V_{BAT}$ .

Similarly, when  $V_{\text{IN}}$  falls below  $V_{\text{BAT}},\ Q4$  turns off, blocking battery current flow into VIN.

## Input Supply Low-Voltage Detection

The IC continuously monitors  $V_{PWRIN}$  during charging. If the input voltage for the active charging source falls below 3.7 V, the IC terminates charging, pulses the STAT pin, sets STAT bits to 11, and sets the FAULT bits to 011 for the appropriate input source.

If the power source recovers above the  $V_{\text{IN}(MIN)}$  rising threshold after timer  $t_{\text{INT}}$  (about two seconds), the charging process is repeated. This prevents the USB power bus from collapsing or oscillating when the IC is connected to a suspended USB port or an OTG device with low current capability.

#### **Input Over-Voltage Detection**

When V<sub>BUS</sub> exceeds its OVP threshold, the IC:

- 1. Turns off Q3:
- 2. Suspends charging from V<sub>BUS</sub>; and
- Sets the FAULTU bits to 001, STATU bits to 11, and pulses the STAT pin.

When  $V_{BUS}$  falls to about 150 mV below  $VBUS_{OVP}$ , the fault is cleared, and charging resumes after  $V_{BUS}$  is revalidated.

If V<sub>IN</sub> exceeds its OVP threshold, the IC:

- 1. Turns off Q4;
- 2. Suspends charging from V<sub>IN</sub>; and
- Sets the FAULTV bits to 001, STATV bits to 11, and pulses the STAT pin.

## **Charge Mode Battery Detection & Protection**

## **VBAT Over-Voltage Protection**

The OREG voltage regulation loop prevents  $V_{BAT}$  from overshooting the OREG voltage by more than 50 mV when the battery is removed. When the PWM charger is running with no battery, the TE bit is not set, and a battery is inserted that's charged to a voltage higher than  $V_{OREG}$ ; PWM pulses stop. If no further pulses occur for 30 ms, the IC sets the FAULT bits to 100, STAT bits to 11, and pulses the STAT pin.

#### **Battery Detection During Charging**

The IC can detect presence, absence, or removal of a battery. During normal charging, once  $V_{\text{BAT}}$  is greater than  $V_{\text{OREG}}-V_{\text{RCH}}$  and the termination charge current is detected; the IC terminates charging and sets the STAT bits to 10. It then turns on a discharge current,  $I_{\text{DETECT}}$ , for  $t_{\text{DETECT}}$ . If  $V_{\text{BAT}}$  is still above  $V_{\text{OREG}}-V_{\text{RCH}}$ , the battery is present and the IC sets the FAULT bits to 000. If  $V_{\text{BAT}}$  is below  $V_{\text{OREG}}-V_{\text{RCH}}$ , the battery is absent and the IC:

- 1. Sets the registers to their default values;
- 2. Sets the FAULT bits to 111; and
- Resumes charging with default values after delay t<sub>INT</sub>.

#### **Battery Detection During Power-up**

At PWRIN POR, if the charger is in 15-Minute Mode (no  $I^2$ C writes from the host detected), the IC starts a 32 ms timer when  $V_{BAT}$  crosses  $V_{SHORT}$  and starts PWM charging. If  $V_{BAT}$  exceeds 3.7 V within a 32 ms period, the IC determines that the battery is not present and:

- Enters Charge Configuration Mode:
- Sets the FAULT bits to 111 (no battery) and resets the SAFETY registers; and
- 3. Disables auto-charging until the next PWRIN POR.

#### **Battery Short-Circuit Protection**

If the battery voltage is below the short-circuit threshold ( $V_{SHORT}$ ); a linear current source,  $I_{SHORT}$ , supplies VBAT until  $V_{BAT} > V_{SHORT}$ .

#### **Charger Status / Fault Status**

The STAT pin indicates the operating condition of the IC and provides a fault indicator for interrupt-driven systems. When a fault condition occurs, the STAT pin pulses LOW for 125  $\mu$ s. If a new fault replaces the prior fault, STAT issues a new pulse.

The FAULT bits (R0[2:0]) indicate the type of fault in Charge Mode (see Table 14). FAULT bits return to 000 once R0 is read if the fault condition has cleared.

#### **Charge Mode Control Bits**

When set, the HZ\_VBUS and HZ\_VIN bits prevent charging from the VBUS or VIN input sources, respectively. The DIS pin prevents all charging when set, regardless of the state of the HZ bits.

Table 6. DIS Pin and HZ Bit Functionality

Charging	DIS PIN	HZ
ENABLE	0	0
DISABLE	X	1
DISABLE	1	X

#### **Boost Mode**

Boost Mode can be enabled when the IC is in 32-Second Mode (host sets TMR\_RST before the  $t_{32SEC}$  expired ) with the OTG pin and OPA\_MODE bits as indicated in Table 7. The OTG ACTIVE state is 1 if OTG\_PL =1, and 0 when OTG\_PL =0.

If boost is active using the OTG pin, boost mode is initiated even if the HZ\_VBUS = 1. The HZ\_VBUS bit overrides the OPA MODE bit.

**Table 7. Enabling Boost** 

OTG_E N	OTG PIN	HZ_VBU S	OPA_MOD E	BOOS T
1	ACTIVE	X	Χ	Enabled
1	Х	0	1	Enabled
1	ACTIVE	0	0	Disabled
1	ACTIVE	Х	0	Disabled
0	Х	1	X	Disabled

To remain in Boost Mode, the TMR\_RST bit must be set by the host before the  $t_{32SEC}$  timer expires. If  $t_{32SEC}$  times out in Boost Mode; the IC reverts to High-Impedance Mode, pulses the STAT pin, sets the FAULT bits to 110, and resets the BOOST bit. POR or USB activity clears the fault condition.

The IC can operate its boost regulator while simultaneously charging from VIN. If the IC is charging from VIN when the boost regulator is enabled, charging pauses until the boost soft-start has completed.

#### **Boost PWM Control**

The IC uses a minimum on-time, and computed minimum off-time, to regulate  $V_{\text{BUS}}$ . The computed off-time is designed to keep the switching frequency constant near 3 MHz when the regulator's inductor current is continuous (CCM).

The regulator achieves excellent transient response by employing current-mode modulation. This technique causes the regulator to exhibit a load line. During CCM Mode, the output voltage drops slightly as the input current rises. With a constant  $V_{\text{BAT}}$ , this appears as a constant output resistance.

The "droop" caused by the output resistance when a load is applied allows the regulator to respond smoothly to load transients with no undershoot from the load line. This can be seen in Figure 34.

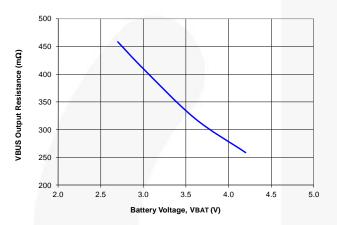


Figure 53. Output Resistance (ROUT)

 $V_{BUS}$  as a function of  $I_{LOAD}$  can be computed when the regulator is in PWM Mode (continuous conduction) as:

$$V_{BUS} = 5.05 - R_{OUT} \bullet I_{IOAD}$$
 EQ. 1

At 3.6  $V_{BAT}$  and  $I_{LOAD} = 300$  mA,  $V_{BUS}$  would droop to about:

$$V_{BLIS} = 5.05 - 0.32 \cdot 0.3 = 4.95V$$
 EQ. 2

At 2.7  $V_{BAT}$ , with  $I_{LOAD} = 200$  mA,  $V_{BUS}$  would droop to about:

$$V_{BLIS} = 5.05 - 0.45 \cdot 0.2 - 4.96V$$
 EQ. 3

#### Pulse Frequency Modulated (PFM) Mode

If  $V_{BUS} > VREF_{BOOST}$  (nominally 5.05 V) when the minimum off time has ended, the regulator enters PFM Mode. Boost pulses are inhibited until  $V_{BUS} < VREF_{BOOST}$ . The minimum on-time is increased to enable the output to pump up sufficiently with each PFM boost pulse. The regulator behaves like a constant on-time regulator, with the bottom of its output voltage ripple at 5.05 V in PFM Mode. Since PFM voltage ripple is typically 20 mV<sub>P-P</sub>, VBUS<sub>(PFM)</sub> is nominally 5.06 V.

**Table 8. Boost PWM Operating States** 

State	Description	Invoked When:
SCHK	Short-Circuit Check	$V_{BAT} > V_{BUS}$ and $V_{BUS} < 1V$
LIN1	Linear Startup	V <sub>BAT</sub> > 1V
SS	Boost Soft-Start	$V_{BUS} < V_{BST}$
BST	Boost Operating Mode	$V_{BAT} > V_{UVLO}$ and SS completed

#### **Shutdown State**

When the boost regulator is shut down, Q3 is off, preventing current flow from VBAT to VBUS. Q1 is also off, which prevents current flow from VBUS to VBAT.

#### **SCHK State**

The SCHK state turns on a switch with an on-resistance of about 120  $\Omega$  from VBAT to VBUS and waits for V<sub>BUS</sub> to rise to about 1 V before proceeding with boost soft-start. This prevents high current drain from the battery, which could occur if Q3 is turned on into a short circuit. If V<sub>BUS</sub> fails to rise above 1 V within 8 ms, a boost overload fault is enunciated.

#### LIN1 State

A portion of Q3 is turned on (on-resistance = 1  $\Omega$ ) to charge V<sub>BUS</sub> from 1V to V<sub>PMID1</sub>. V<sub>PMID1</sub> is about 0.7 V below V<sub>BAT</sub>. This state ends when V<sub>PMID1</sub> - V<sub>BUS</sub> < 0.4 V. If V<sub>BUS</sub> fails to achieve V<sub>PMID1</sub> - 0.4 V within 512  $\mu$ s, a boost overload fault is enunciated.

#### SS State

When  $V_{\text{BUS}} > V_{\text{PMID1}} - 0.4 \text{ V}$ , the boost regulator begins switching. The output slews up until  $V_{\text{BUS}}$  is within 10% of its setpoint; at which time, the regulation loop is closed and the boost reference is digitally stepped to 5.07 V.

If the output fails to achieve 90% of its setpoint ( $V_{BST}$ ) within 512  $\mu s$ , a boost overload fault is enunciated.

#### **BST State**

This is the normal operating mode of the regulator.

#### **Thermal**

If the die temperature reaches 120°C while the boost and charger are both operating, charging stops for at least 10 ms, then resumes when the die temperature falls below 120°C.

#### **Boost Fault States**

A BOOST fault is enunciated by the STAT pin pulsing and FAULT status bits under any of the following conditions.

Table 9. Fault Status Bits during Boost Mode

Fault Bit		Bit	Fault Description					
B2	В1	В0	Fault Description					
0	0	0	Normal (no fault)					
0	0	1	$V_{BUS} > VBUS_{OVP}$					
0	1	0	V <sub>BUS</sub> fails to achieve the voltage required to advance to the next state during soft-start or sustained (>32 ms) current limit during the BST state.					
0	1	1	V <sub>BAT</sub> < UVLO <sub>BST</sub>					
1	0	0	N/A: This code will not appear					
1	0	1	Thermal shutdown					
1	1	0	Timer fault					
1	1	1	N/A: This code will not appear					

Once a fault is triggered, the OPA\_MODE bit is reset.

If the boost was started by setting the OTG pin and OTG\_EN bits, the boost attempts to restart after a fault following a "cool-off" time of 128 ms.

#### **VREF**

The VREF pin provides bias current to the charging circuit while VIN is the power source. This pin follows PMID2, but its voltage is limited to 5.8 V. Up to 5 mA of current can be drawn from the VREF pin to power external devices.

#### **LED Control**

An LED driver provides a constant current to drive the anode of a charge indicator LED. The LED flashes during charging. The LED\_CONTROL register provides control of the LED driver and can be programmed to flash the LED when charging is disabled.

LED\_CONTROL is reset whenever the IC begins charging in 15-Minute Mode. This occurs after VBUS or VIN POR with a weak battery when  $t_{32SEC}$  is not running or when  $t_{32SEC}$  expires.

## **Recommended PCB Layout**

To limit the high-voltage excursions and stresses on the chargers' internal switching MOSFETs, it is critical to limit the total loop length from PMID back to the GND return, including the length of the CMID bypass capacitors. The layout below achieves this goal.

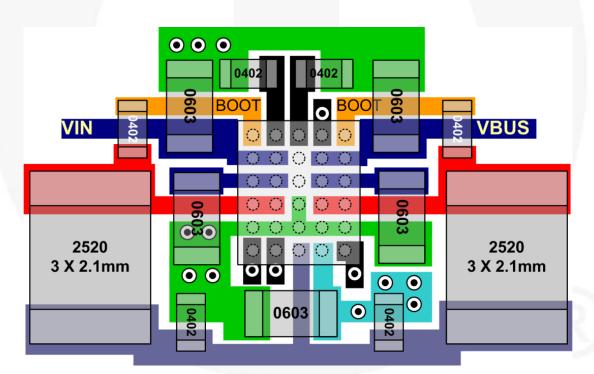


Figure 54. Recommended Layout for High-Current Charging, Using 2520 Inductors

### I<sup>2</sup>C Interface

The serial interface is compatible with Standard, Fast, Fast Plus, and High-Speed Modes per the I<sup>2</sup>C-Bus® specifications. The SCL line is an input and its SDA line is a bi-directional open-drain output; it can only pull down the bus when active. The SDA line only pulls LOW during data reads and when signaling ACK. All data is shifted in MSB (bit 7) first.

## **Bus Timing**

As shown in Figure 55, data is normally transferred when SCL is LOW. Data is clocked in on the rising edge of SCL. Typically, data transitions shortly at or after the falling edge of SCL to allow ample time for the data to set up before the next SCL rising edge.

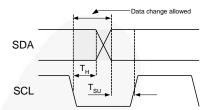


Figure 55. Data Transfer Timing

Each bus transaction begins and ends with SDA and SCL HIGH. A transaction begins with a START condition, which is defined as SDA transitioning from 1 to 0 with SCL HIGH, as shown in Figure 56.

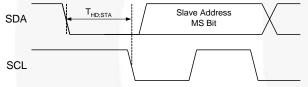


Figure 56. Start Bit

A transaction ends with a STOP condition, which is defined as SDA transitioning from 0 to 1 with SCL HIGH, as shown in Figure 57.

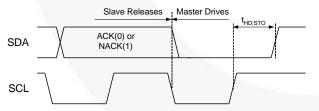


Figure 57. Stop Bit

During a read from the FAN54300 (see Figure 60), the master issues a "REPEATED START" after sending the register address and before resending the slave address. The REPEATED START is a 1-to-0 transition on SDA while SCL is HIGH, as shown in Figure 58.

## High-Speed (HS) Mode

The protocols for High-Speed (HS), Low-Speed (LS), and Fast-Speed (FS) Modes are identical, except the bus speed for HS Mode is 3.4 MHz. HS Mode is entered when the bus master sends the HS master code 00001XXX after a START condition. The master code is sent in Fast or Fast-Plus Mode (less than 1 MHz clock). Slaves do not ACK this transmission.

The master then generates a REPEATED START condition (see Figure 58) that causes all slaves on the bus to switch to HS Mode. The master then sends I<sup>2</sup>C packets, as described above, using the HS Mode clock rate and timing.

The bus remains in HS Mode until a stop bit (Figure 57) is sent by the master. While in HS Mode, packets are separated by REPEATED START conditions (Figure 58).

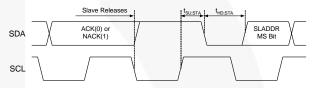


Figure 58. Repeated Start Timing

#### **Read and Write Transactions**

The following figures outline the sequences for data read and write. Bus control is signified by the shading of the packet,

defined as

Master Drives Bus and Slave Drives Bus All addresses and data are MSB first.

Table 10. Bit Definitions for Figure 59 and Figure 60

Symbol	Definition
S	START, see Figure 56.
Α	ACK. The slave drives SDA to 0 to acknowledge the preceding packet.
Ā	NACK. The slave sends a 1 to NACK the preceding packet.
R	Repeated START, see Figure 58
Р	STOP, see Figure 57.



Figure 59. Write Transaction



Figure 60. Read Transaction

## **Register Descriptions**

## Table 11. I<sup>2</sup>C Slave Address

	0	1	2	3	4	5	6	7	Hex
VIN Charger	R/W	0	1	0	1	0	1	1	D4
USB Charger	R/W	1	1	0	1	0	1	1	D6

## Table 12. I<sup>2</sup>C Register Address

Name	Register Address	Slave Address	Affects	7	6	5	4	3	2	1	0
CONTROL0_U	0	D6	USB	0	0	0	0	0	0	0	0
CONTROL1_U	1	D6	USB	0	0	0	0	0	0	0	1
OREG_U	2	D6	USB	0	0	0	0	0	0	1	0
IC_INFO_U	3	D6	Both	0	0	0	0	0	0	1	1
IBAT_U	4	D6	USB	0	0	0	0	0	1	0	0
SP_CHARGER_U	5	D6	USB	0	0	0	0	0	1	0	1
SAFE_U	6	D6	USB	0	0	0	0	0	1	1	0
CONTROL0_V	0	D4	VIN	0	0	0	0	0	0	0	0
CONTROL1_V	1	D4	VIN	0	0	0	0	0	0	0	1
OREG_V	2	D4	VIN	0	0	0	0	0	0	1	0
IC_INFO_V	3	D4	Both	0	0	0	0	0	0	1	1
IBAT_V	4	D4	VIN	0	0	0	0	0	1	0	0
SP_CHARGER_V	5	D4	VIN	0	0	0	0	0	1	0	1
SAFE_V	6	D4	VIN	0	0	0	0	0	1	1	0
LED_CONTROL	7	D4/D6	Both	0	0	0	0	0	1	1	1
CHARGE_STATUS	8	D4/D6	Both	0	0	0	0	1	0	0	0
INPUT_STATUS	9	D4/D6	Both	0	0	0	0	1	0	0	1
DIE_REV	14	D4/D6	Both	0	0	0	1	0	1	0	0

## **Register Bit Definitions**

TMR_RST	Bit	Name	Туре					Description					
OTG	CON	NTROL0_U	I.				Reg Addr: 0	Slave Addr: D6 Default = x	1xx xxxx				
OTG	7	TMR_RST	W	Writ	Writing a 1 resets the t <sub>32SEC</sub> timer. Writing a 0 has no effect.								
STAT_U	<b>'</b>	OTG	R	Retu	Returns the OTG pin level (1 = OTG pin HIGH)								
STAT_U	6	EN_STU	R/W				•	charging from USB source.					
STAT_U													
STAT_U				Tab	le 1	3. L	ISB Charger Status Bits						
10   Charge in progress from USB source     10   Charge done     11   USB charger fault     3   BOOST   R   0: OTG boost is not active.     1: OTG boost is active.     Delineates USB Charger and OTG Boost Faults     Table 14. USB Fault Bits     Bits	E. 1	STAT_U	ь		00		Normal (no fault) / Ready						
11	5.4		IX		01		Charge in progress from U	Charge in progress from USB source					
3   BOOST   R   0: OTG boost is not active.					10		Charge done						
Second   S					11		USB charger fault						
FAULT_U   R     Table 14. USB Fault Bits     Bits     Charger Mode   Boost Mode	3	BOOST	R		_	-							
FAULT_U   R							st Faults						
PAULT_U							OD I dan Dits						
2:0 FAULT_U  R  0 0 0 Normal (no fault)  V <sub>BUS</sub> > VBUS <sub>OVP</sub> V <sub>BUS</sub> > VBUS <sub>OVP</sub> 0 1 0 Sleep Mode: V <sub>BUS</sub> < V <sub>BAT</sub> Boost overload  0 1 1 Poor USB input source V <sub>BAT</sub> < UVLO <sub>BST</sub> 1 0 0 Battery OVP N/A: This code will not appear  1 0 1 Thermal shutdown Thermal shutdown  1 1 0 Timer fault  Timer fault							Charger Mode	Boost Mode	A				
2:0   FAULT_U				l <del></del>	0		Normal (no fault)	Normal (no fault)					
0 1 0 Sleep Mode: V <sub>BUS</sub> < V <sub>BAT</sub> Boost overload 0 1 1 Poor USB input source V <sub>BAT</sub> < UVLO <sub>BST</sub> 1 0 0 Battery OVP N/A: This code will not appear 1 0 1 Thermal shutdown Thermal shutdown 1 1 0 Timer fault Timer fault				0	0	1	V <sub>BUS</sub> > VBUS <sub>OVP</sub>	V <sub>BUS</sub> > VBUS <sub>OVP</sub>					
1 0 0 Battery OVP N/A: This code will not appear 1 0 1 Thermal shutdown Thermal shutdown 1 1 0 Timer fault Timer fault	2:0	FAULT_U	R	0	1	0	Sleep Mode: V <sub>BUS</sub> < V <sub>BAT</sub>	Boost overload	-				
1 0 1 Thermal shutdown Thermal shutdown 1 1 0 Timer fault Timer fault				0	1	1	Poor USB input source	V <sub>BAT</sub> < UVLO <sub>BST</sub>					
1 1 0 Timer fault Timer fault				1	0	0	Battery OVP	N/A: This code will not appear					
				1 0 1 Thermal shutdown			Thermal shutdown	Thermal shutdown					
1 1 1 No hattery N/A: This code will not appear				1	1	0	Timer fault	Timer fault					
				1	1	1	No battery	N/A: This code will not appear					

## Note:

7. Default values are in **bold** text.

Bit	Name	Туре	Description							
COI	NTROL1_U		Reg Addr: 1 Slave Addr: D6 Default = 0011 0000							
			USB bus current limit							
			Table 15. IBUSLIM: USB bus current limit							
			[7:6] IBUS Current Limit							
7:6	IBUSLIM	R/W	00 100 mA							
			01 500 mA							
			10 800 mA							
			11 No limit							
			Weak Battery Threshold. This register determines $V_{\text{LOWV}}$ threshold when $V_{\text{BUS}}$ is charging.							
			Table 16. V <sub>LOWV</sub> : Weak Battery Threshold							
		- 2	[5:4] IBUS Current Limit							
5:4	VLOWV_U	R/W	00 3.4 V							
			01 3.5 V							
	- 4		10 3.6 V							
	//		11 3.7 V							
3	TE_U	R/W	<ul><li>0: Charge termination is disabled when charging from USB.</li><li>1: Charge termination is enabled for USB charging.</li></ul>							
			0: USB charger is enabled.							
2	CE#_U	R/W	1: USB charger is disabled. This bit is set when $t_{15\text{MIN}}$ expires, regardless of which input source is charging.							
1	HZ_U	R/W	0: USB charger is not in High-Impedance Mode.							
•	112_0	10,00	1: USB charger is in High-Impedance Mode.							
0	OPA_ MODE	R/W	Boost Mode disabled unless enabled with the OTG pin and OTG_EN HIGH.     Boost Mode enabled unless HZ U is set.							
OPE	EG_U		1: Boost Mode enabled unless HZ_U is set.  Reg Addr: 2 Slave Addr: D6 Default = 0000 1010							
			Charger output "float" voltage when charging from USB source.							
7:2	OREGU	R/W	Programmable from 3.5 to 4.44 V in 20 mV increments. Defaults to 000010 (3.54 V) (see Table 5).							
1	OTG_PL	R/W	0: OTG pin is active LOW.							
'	OIG_IL	17/ 7/	1: OTG pin is active HIGH.							
0	OTG_EN	R/W	<ul><li>OTG pin does not enable boost when HIGH.</li><li>OTG pin enables boost when HIGH.</li></ul>							
IC_I	INFO_U		Reg Addr: 3 Slave Addr: D4 or D6 Default = 100x x000							
7:5	VENDOR	R	100: Identifies Fairchild as the supplier.							
4:3	PN_U	R	Part number bits. FAN54300 = 10							
2:0	REV	R	IC Revision. Revision is 1.X where X is the decimal of these 3 bits.							
DIE	_REV		Reg Addr: 14H Slave Addr: D4 or D6 Default = 0000 XXXX							
7:4	Reserved	R	These bits return 0.							
3:0	REV_D	R	Die revision. These bits uniquely identify the full revision of the IC. REV bits change whenever there a significant design change. REV_D bits change whenever any masks are revised.							

Bit	Name	Туре							Descr	iption
IBAT	_U			Re	g Addr:	4			Slav	ve Addr: D6 Default = 0000 1001
7	RESETU	W								ave address D4, except the Safety register Read returns 0.
			Sets th	e max	imum ch	arge c	urrent (	I <sub>CHARGE</sub> )	when o	charging from VBUS when IO_LEVELU = 0.
			Table	17. l	CHARGE A	s a F	unctio	n of th	e ICHG	GU Bits and R <sub>SENSE</sub> Resistor Value
			BIN	НЕ	X V <sub>RSE</sub>		OCHARGE			1
					(m)			100mΩ		
			000	0			550	374	704	
6:4	ICHGU	R/W	001	0			650	442	832	
• • •			010	0.		_	750	510	960	
			011	0			850	578	1088	
			100	0			950 1,050	646 714	1216 1344	
			110	0		_	1,150	782	1472	
			111	0			1,250	850	1600	
						-				ger current is limited to 1250 mA ( $R_{SENSE} = 68m\Omega$ ).
3	Reserved	R	This bit						o, o	ger earreit e minteu te 1200 m. (102No2 001122).
	- /		Sets th	e curre	ent at wh	ich ch	arging t	erminat	es whei	n charging from VBUS if the TE bit is set.
				18. l	CHARGE T					Function of ITERM bits and R <sub>SENSE</sub>
	- 6		BIN	HEX	V <sub>RSENSE</sub>	I <sub>TER</sub>	<sub>M</sub> (mA)			
			DIII	IILA	(mV)		100mΩ	2		
			000	00	3.3	49	33			
2:0	ITERMU	R/W	001	01	6.6	97	66			
			010	02	9.9	146	99			
			011	03	13.2	194	132			
			100	04	16.5	243	165			
			101	05	19.8	291	198			
			110	06	23.1	340	231			
			111	07	26.4	388	264			

Bit	Name	Туре	Description								
SP_	CHARGER_U	J	Reg Addr: 5	Slave Addr: D6 Default = 0x1x x100							
7	Reserved	R	This bit returns 0.								
6	VBUS_CON	R	Mirror of INPUT_STATUS[5] (se	Mirror of INPUT_STATUS[5] (see INPUT_STATUS register description)							
5	IO_LEVEL	R/W	•	by IOCHARGE bits for charging from VBUS. The voltage across $R_{\text{SENSE}}$ for output current control is set to 68 m $\Omega$ , 221 mA for 100 m $\Omega$ ).							
4	SPU	R	VBUS is not PWM charging.	Special charger loop is not active. Input power source is able to stay above V <sub>SP</sub> . SPU = 0 when VBUS is not PWM charging.  1: Special charger loop is active and controlling the charging current.							
3	VIN_CON	R	Mirror of INPUT_STATUS[7] (see INPUT_STATUS register description)								

Bit	Name	Туре	Description							
								ence voltage when charging from $V_{BUS}$ . If $V_{BUS}$ falls sed until the input voltage is at or above $V_{SP}$ .		
			Table 1	9 V	Snecial	Charge	r Refer	ence Voltage		
			DEC	BIN	V <sub>SP</sub>	Onlarge	, INCICI	choc voltage		
			0	000	4.21					
2:0	VSPU	R/W	1	001	4.29					
2.0	VSFU	IK/VV	2	010	4.37					
			3	011	4.45					
			4	100	4.53					
			5	101	4.61					
			6	110	4.69					
			7	111	4.77					
	E_U			eg Add				Slave Addr: D6 Default = 0100 0000		
7	Reserved	R	This bit	returns (	).					
			Any atte		rite a val	ue to IC	HGU hig	her than the contents of ISAFEU sets ICHGU =		
			Table 2	20. USE		ng I <sub>CHA</sub>	<sub>RGE</sub> Lim	it as a Function of the ISAFEU Bits		
			BIN	HEX	V <sub>RSENSE</sub>		(mA)			
					(mV)	68mΩ	100mΩ			
6:4	ISAFEU	R/W	000	00	37.4 44.2	550 650	374 442			
			010	02	51.0	750	510			
	, in		011	03	57.8	850	578			
		1	100	04	64.6	950	646			
			101	05 06	71.4 78.2	1,050 1,150	714 782			
			111	07	85.0	1,150	850			
			(below)  Table 2	results ii	n OREGU	J = Max	OREG.	at is higher than the value in the Max. OREG column of the VSAFEU Bits when Charging from		
		A	VBUS		Max O	REG	VOREG	1		
			DEC	BIN	(REG2		MAX			
			0	0000	1000		4.20			
			II 1	0001	1001		4.22 4.24			
			<del>                                 </del>	0010	1 /1/11					
			2	0010 0011	1001					
3:0	VSAFFII	RM	<del>                                 </del>	0010 0011 0100	1001 1001 1001	10	4.26			
3:0	VSAFEU	R/W	2	0011	1001	110	4.26			
3:0	VSAFEU	R/W	2 3 4 5 6	0011 0100 0101 0110	1001 1001 1010 1010	110	4.26 4.28 4.30 4.32			
3:0	VSAFEU	R/W	2 3 4 5 6 7	0011 0100 0101 0110 0111	1001 1001 1010 1010	110 111 000 001 010	4.26 4.28 4.30 4.32 4.34			
3:0	VSAFEU	R/W	2 3 4 5 6 7 8	0011 0100 0101 0110 0111 1000	1001 1001 1010 1010 1010	110 111 000 001 010 011	4.26 4.28 4.30 4.32 4.34 4.36			
3:0	VSAFEU	R/W	2 3 4 5 6 7 8	0011 0100 0101 0110 0111 1000 1001	1001 1001 1010 1010 1010 1010	110 111 1000 1001 1000 111 1000	4.26 4.28 4.30 4.32 4.34 4.36 4.38			
3:0	VSAFEU	R/W	2 3 4 5 6 7 8 9	0011 0100 0101 0110 0111 1000 1001	1001 1001 1010 1010 1010 1011 1011	110 111 1000 1001 1010 1010 1000 1011	4.26 4.28 4.30 4.32 4.34 4.36 4.38 4.40			
3:0	VSAFEU	R/W	2 3 4 5 6 7 8 9 10	0011 0100 0101 0110 0111 1000 1001 1010	1001 1010 1010 1010 1010 1011 1011	110 111 1000 101 1010 1011 100 101	4.26 4.28 4.30 4.32 4.34 4.36 4.38 4.40 4.42	R		
3:0	VSAFEU	R/W	2 3 4 5 6 7 8 9	0011 0100 0101 0110 0111 1000 1001	1001 1001 1010 1010 1010 1011 1011 101	110 111 000 001 010 011 100 101 110	4.26 4.28 4.30 4.32 4.34 4.36 4.38 4.40	R		
3:0	VSAFEU	R/W	2 3 4 5 6 7 8 9 10 11	0011 0100 0101 0110 0111 1000 1001 1010 1011 1100	1001 1010 1010 1010 1010 1011 1011	110 111 1000 101 101 100 101 100 111 100 111	4.26 4.28 4.30 4.32 4.34 4.36 4.38 4.40 4.42 4.44	R		

Bit	Name	Type	Description					
CON	NTROL0_V		Reg Addr: 0 Slave Addr: D4 Default = x1xx 0xxx					
	TMR_RST	W	Writing a 1 resets the t <sub>32SEC</sub> timer. Writing a 0 has no effect.					
	SRST	R	Returns the SRST pin level (1 = SRST pin HIGH).					
6	EN_STV	R/W	<ul> <li>STAT pin does not go LOW when charging from V<sub>IN</sub> source.</li> <li>STAT pin function is enabled for V<sub>IN</sub> source.</li> </ul>					
			-					
		R	Table 22. VIN Charger Status Bits					
E. 1	STAT_V		00 Normal (no fault)					
5:4		ĸ	01 Charge in progress from VIN source					
			10 Charge Done					
			11 VIN charger fault					
3	Reserved	R	This bit returns 0.					
			Delineates VIN Charger Faults					
			Table 23. VIN Charger Fault Bits					
	- 4		Bits Charger Mode					
			2 1 0 Charger Mode					
			0 0 0 Normal (no fault)					
2:0	FAULT_V	R	0 0 1 V <sub>IN</sub> > VIN <sub>OVP</sub>					
0	17.021_		0 1 0 Sleep Mode: V <sub>IN</sub> < V <sub>BAT</sub>					
			0 1 1 Poor VIN input source					
			1 0 0 Battery OVP					
			1 0 1 Thermal shutdown					
					1 1 0 Timer fault			
			1 1 1 No battery					
CON	NTROL1_V		Reg Addr: 1 Slave Addr: D4 Default = 0111 0000					
7:6	Reserved	R/W	These bits have no effect on IC operation. Input current is not limited by the IC when charging from VIN.					
5:4	VLOWV_V	R/W	See Table 16. VLOWV: Weak Battery Threshold					
3	TE_V	R/W	0: Charge termination is disabled when charging from VIN.					
			1: Charge termination is enabled for VIN charging.					
2	CE#_V	R/W	<ul> <li>VIN charger is enabled.</li> <li>VIN charger is disabled. This bit is set when t<sub>15MIN</sub> expires, regardless of which input source is</li> </ul>					
_	OL#_V	10,00	charging.					
1	U7 \/	R/W	0: VIN charger is not in High-Impedance Mode.					
1	HZ_V	K/VV	1: VIN charger is in High-Impedance Mode.					
0	Reserved	R	This bit returns 0.					
ORE	G_V	1	Reg Addr: 2 Slave Addr: D4 Default = 0000 1010					
7:2	OREGV	R/W	Charger output "float" voltage when charging from VIN source.  Programmable from 3.5 to 4.44 V in 20 mV increments. Defaults to 000010 (3.54 V) (see Table 5).					
1:0	Reserved	R	These bits return 10.					
IC_I	NFO_V		Reg Addr: 3 Slave Addr: D4 Default = 100x x000					
7:5	VENDOR	R	100: Identifies Fairchild as the supplier.					
4:3	PN_V	R	Part number bits: FAN54300 = 00					
2:0	REV	R	IC Revision: Revision is 1.X, where X is the decimal of these 3 bits.					

Bit	Name	Туре						ļ	Des	scription	
IBA	T_V		•	R	eg Add	lr: 4				Slave Addr: D4 Default = 0000 0001	
7	RESETV	W								slave address D4, except the Safety register (Registerns 0.	j6),
			Sets the	maxin	num ch	arge c	urrent (I	CHARGE) W	hen	n charging from VIN when IO_LEVELV = 0.	
			Table 24	4. I <sub>CHA</sub>	RGE Cu	rrent a	as a Fur	ction of	the	e ICHGV Bits and R <sub>SENSE</sub> Resistor Value	
			BIN	HEX	V <sub>RSE</sub>		OCHARGE 68mΩ	<b>(mA)</b>			
			0000	00	37.		550	374			
			0001	01	44.		650	442			
			0010	02	51.		750	510			
6:3	ICHGV	R/W	0011	03	57.		850	578			
0.5	101101	1 1 / V V	0100	04	64.		950	646			
			0101	05	71.	4 1	1,050	714			
		- 4	0110	06	78.	2 1	1,150	782			
		- 40	0111	07	85.	0 1	1,250	850			
		./*	1000	08	91.	8 1	1,350	918			
			1001	09	98.	6 1	1,450	986			
			1010	0A	105	.4 1	1,550	1,054			
			Any atte	mpt to	write a	value l	higher th	an 1010	resu	ults in ICHGV = 1010.	
			Table 2	25. I <sub>CH</sub>	ARGE TO					the TE bit is set:  a Function of the ITERM bits and R <sub>SENSE</sub>	
			Resisto	or Val	ue						
			BIN I	768	RSENSE (mV)		<b>(mA)</b> 100mΩ	}			
			000	00	3.3	49	33				
2:0	ITERMV	R/W	001	01	6.6	97	66				
			010	02	9.9	146	99				
					13.2	194	132				
					16.5	243	165				
			101	05	19.8	291	198				
			110	06	23.1	340	231				
			111	07	26.4	388	264				

Bit	Name	Туре		Description					
SP_	CHARGER_V		Reg Addr: 5	Slave Addr: D4 Default = 0x1x x100					
7	Reserved	R	This bit returns 0.						
6	VIN_CON	R	Mirror of INPUT_STATUS[7] (see	INPUT_STATUS register description)					
5	IO_LEVELV	R/W	•	y IOCHARGE bits for charging from VIN. ge across $R_{\text{SENSE}}$ for output current control is set to 22.1mV A for 100m $\Omega$ ).					
4	SPV	R	charging.	$V_{IN}$ is able to stay above $V_{SP}$ . SPV = 0 when VIN is not PWM and controlling the charging current.					
3	EN_LEVEL	R	0: DISABLE (DIS) pin is LOW. 1: DISABLE (DIS) pin is HIGH						
2:0	VSPV	R/W	Sets the special charger control loop reference voltage when charging from VIN. If V <sub>iv.</sub> falls below						

Bit	Name	Туре	Description							
SAFE	_ <b>V</b>	•	F	Reg Ad	dr: 6			Slave Addr: D4 Default = 0100 0000		
			Any atter	npt to w	vrite a val	ue highe	than 10	er than the contents of ISAFEV sets ICHGV = ISAFEV. 10 to ISAFEV results in ISAFEV = 1010. of the ISAFEV Bits when Charging from VIN		
			BIN	HEX	V <sub>RSENSE</sub>	I <sub>SAFE</sub>	(mA)			
			DIN		(mV)	68mΩ	$100 \text{m}\Omega$			
			0000	00	37.4	550	374			
			0001	01	44.2	650	442			
7:4	ISAFEV	R/W	0010	02	51.0	750	510			
			0011	03	57.8	850	578			
			0100	04	64.6	950	646			
			0101	05	71.4	1,050	714			
			0110	06	78.2	1,150	782			
			0111	07	85.0	1,250	850			
			1000	08	91.8	1,350	918			
			1001	09	98.6	1,450	986			
			1010	0A	105.4	1,550	1,054			
3:0	VSAFEV	R/W						t is higher than the value in the Max OREG column a Table 21).		

Bit	Name	Туре		Description						
LED	_CONTROL	•	Reg Addr: 7	Slave Addr: D4 or D6						
		y	Sets LED behavior							
	I_LED		Table 27. LED Control Bits	s						
7:6		R/W	00 LED is off							
7.0		10,00	01 LED current = 1.13 mA							
			10 LED current = 2.25mA							
			11 LED current = 4.50 mA							
5	Reserved	R	This bit returns 0.							
4	LED_ON	R/W	<ul><li>LED is only active when charging.</li><li>LED is active regardless of charging status.</li></ul>							
			Sets LED blink toN							
			Table 28. LED ON-Time							
3:2	LED_TON	R/W	<b>00</b> 131 ms							
3.2	LED_TON	IN/VV	01 262 ms							
			10 524 ms							
			11 Constant ON							
			Sets LED blink t <sub>OFF</sub>							
			Table 29. LED OFF-Time							
1:0	LED_TOFF	R/W	00 393 ms							
1.0	LLD_1011	01 786 ms	01 786 ms							
			<b>10</b> 1573 ms							
			11 3146 ms							

Bit	Name	Туре	Description
CHA	ARGE_STATUS		Reg Addr: 8 Slave Addr: D4 or D6
7	ITERM_CMP	R	0: If TE = 1, $(V_{CSIN} - V_{BAT}) < V_{ITERM}$ . If TE = 0, $(V_{CSIN} - V_{BAT}) < 1 \text{ mV}$ . 1: If TE = 0, $(V_{CSIN} - V_{BAT}) > V_{ITERM}$ . If TE = 0, $(V_{CSIN} - V_{BAT}) > 1 \text{ mV}$ .
6	T_120	R	<ul><li>0: The die temperature is below 120°C.</li><li>1: The die temperature is above 120°C.</li></ul>
5	ICHG	R	<ul><li>10: ICHARGE loop is controlling charge current (charger is in CC Mode).</li><li>11: ICHARGE loop is not controlling charge current.</li></ul>
4	IBUS	R	O: IBUS is limiting charge current.  IBUS loop is not controlling charge current.  This bit always = 1 when charging from VIN.
3	CV	R	1 indicates that the constant-voltage loop (OREG) is controlling the charger and that all current limiting loops have released. Deglitched 32ms.
2	LINCHG	R	<ul> <li>0: Charger is not in Linear Mode</li> <li>1: Charger is in Linear Mode (V<sub>BAT</sub> &lt; V<sub>SHORT</sub>).</li> </ul>
1:0	Reserved	R	These bits always return 0.
INP	UT_STATUS		Reg Addr: 9 Slave Addr: D4 or D6
7	VIN_CON	R	<ul> <li>0: V<sub>IN</sub> has been less than V<sub>BAT</sub> for at least 100ms (VIN is disconnected).</li> <li>1: V<sub>IN</sub> &gt; V<sub>BAT</sub> and V<sub>IN</sub> &gt; 4.5 V for at least 4ms (VIN is connected).</li> <li>This bit is mirrored in SP_CHARGER_U[3] and SP_CHARGER_V[6].</li> </ul>
6	VIN_VALID	R	<ul> <li>0: V<sub>IN</sub> has not passed validation.</li> <li>1: V<sub>IN</sub> has passed validation and can be used as a charging source.</li> </ul>
5	VBUS_CON	R	<ul> <li>0: V<sub>BUS</sub> has been less than V<sub>BAT</sub> for at least 100ms (VBUS is disconnected).</li> <li>1: V<sub>BUS</sub> &gt; V<sub>BAT</sub> and V<sub>BUS</sub> &gt; 4.5 V for at least 4ms (VBUS is connected).</li> </ul>
4	VBUS_VALID	R	<ul> <li>0: V<sub>BUS</sub> has not passed validation.</li> <li>1: V<sub>BUS</sub> has passed validation and can be used as a charging source.</li> <li>This bit is mirrored in SP_CHARGER_U[6].</li> </ul>
3	SOURCE	R	<ul> <li>0: V<sub>IN</sub> is used for IC power and charging.</li> <li>1: V<sub>BUS</sub> is used for IC power and charging.</li> </ul>
2:0	Reserved	R	These bits always return 0.

## **Physical Dimensions**

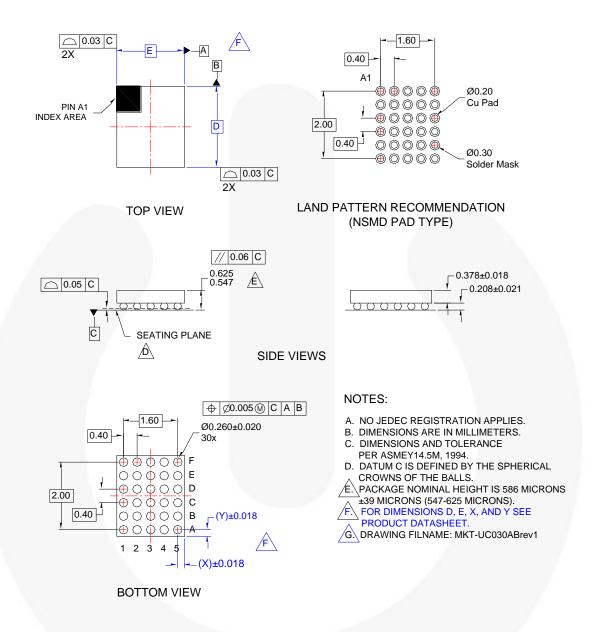


Figure 61. 30-Ball, WLCSP, 5x6 Array, 0.4 mm Pitch, 586 µm Package Height

## **Product-Specific Dimensions**

Product	D	E	X	Y
FAN54300UCX	2.460 ±0.030 mm	2.26 ±0.030 mm	0.330 mm	0.230 mm

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Rev. 165

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